

中国科学院大学
夏季强化课程
2022

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Fast Solvers for Large Algebraic Systems

Lecture 1. Large-scale numerical simulation

1
大规模数值模拟

Table of Contents

- **Lecture 1: Large-scale numerical simulation**
- Lecture 2: Fast solvers for sparse linear systems
- Lecture 3: Methods for non-symmetric problems
- Lecture 4: Methods for nonlinear problems
- Lecture 5: Mixed-precision methods
- Lecture 6: Communication hiding and avoiding
- Lecture 7: Fault resilience and reliability
- Lecture 8: Robustness and adaptivity

Introduction

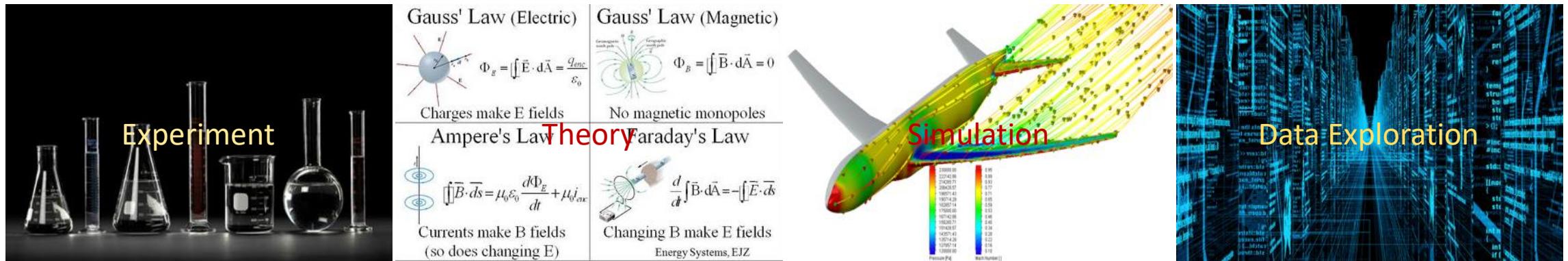
Some applications of computational mathematics

/01

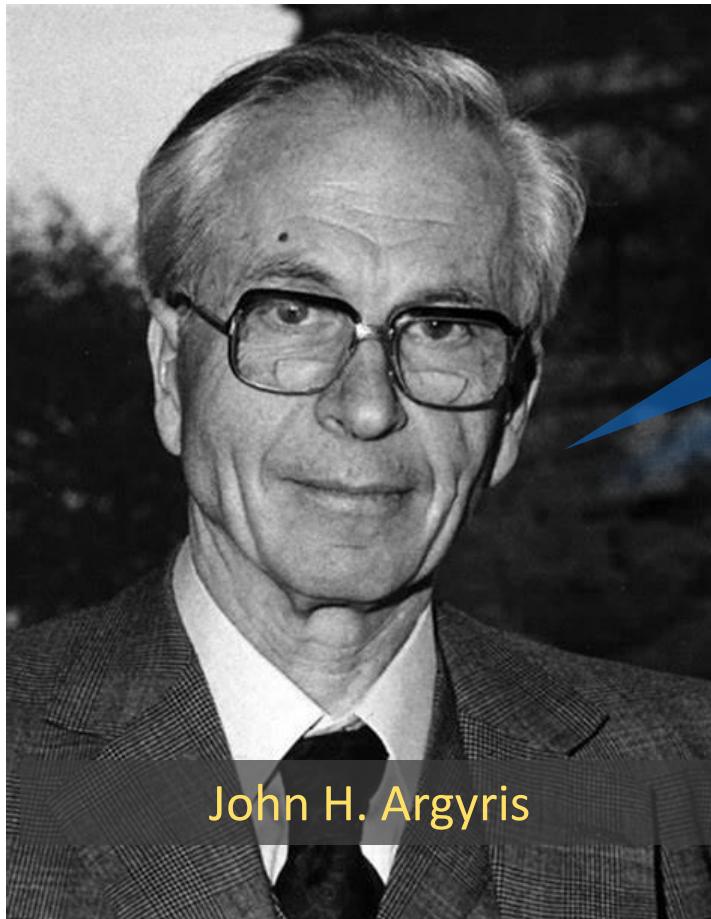
Four Paradigms of Scientific Discovery



The Fourth Paradigm: Data-Intensive Scientific Discovery, Hey, Tansley, Tolle, Microsoft, 2009



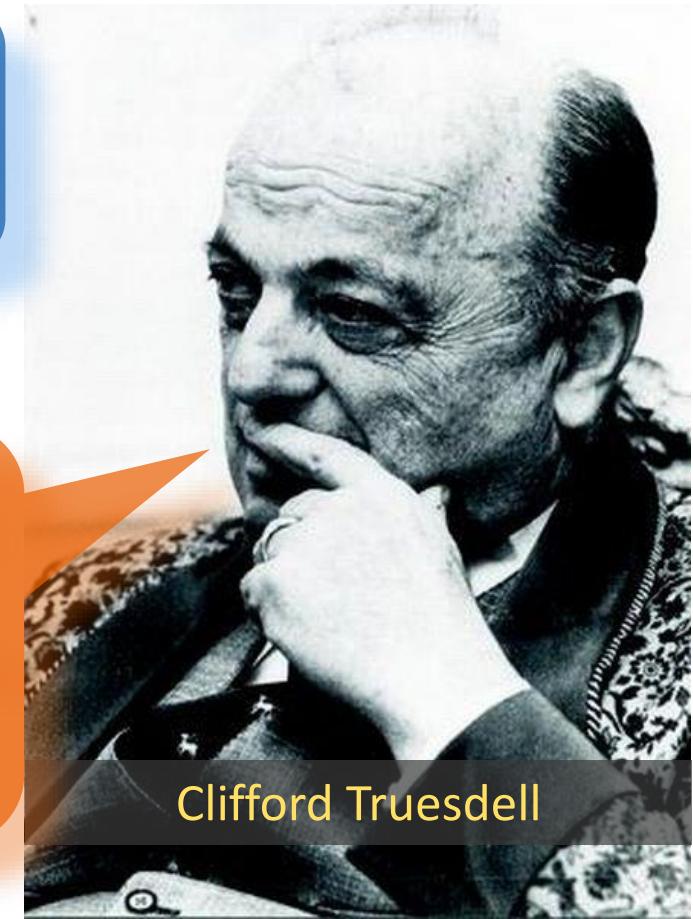
Computer and Science



John H. Argyris

“The computer shapes the theory”,
Paper read to the Royal Aeronautical
Society on May 18, 1965

“The computer: ruin of science and
threat to mankind”, in: An Idiot’s
Fugitive Essays on Science: Methods,
Criticism, Training, Circumstances.
Springer-Verlag, New York, 1984



Clifford Truesdell

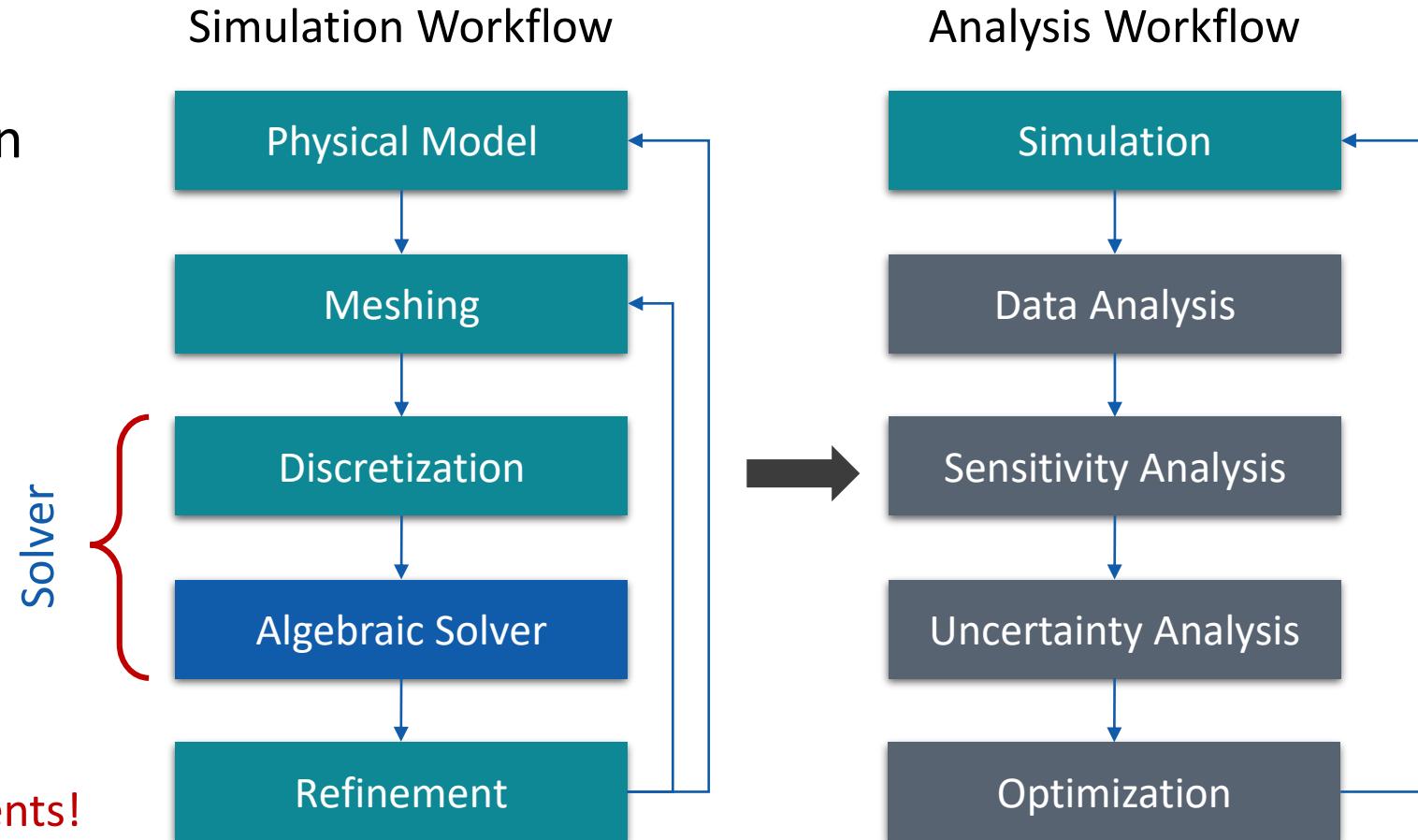
Ref: J.A. Cottrell, A. Reali, Y. Bazilevs, T.J.R. Hughes, “Isogeometric analysis of structural vibrations”, Computer Methods in Applied Mechanics and Engineering, 195, Issues 41–43, 2006,

Why Simulation So Important

In many situations, we have very limited theories and can not do experiments:

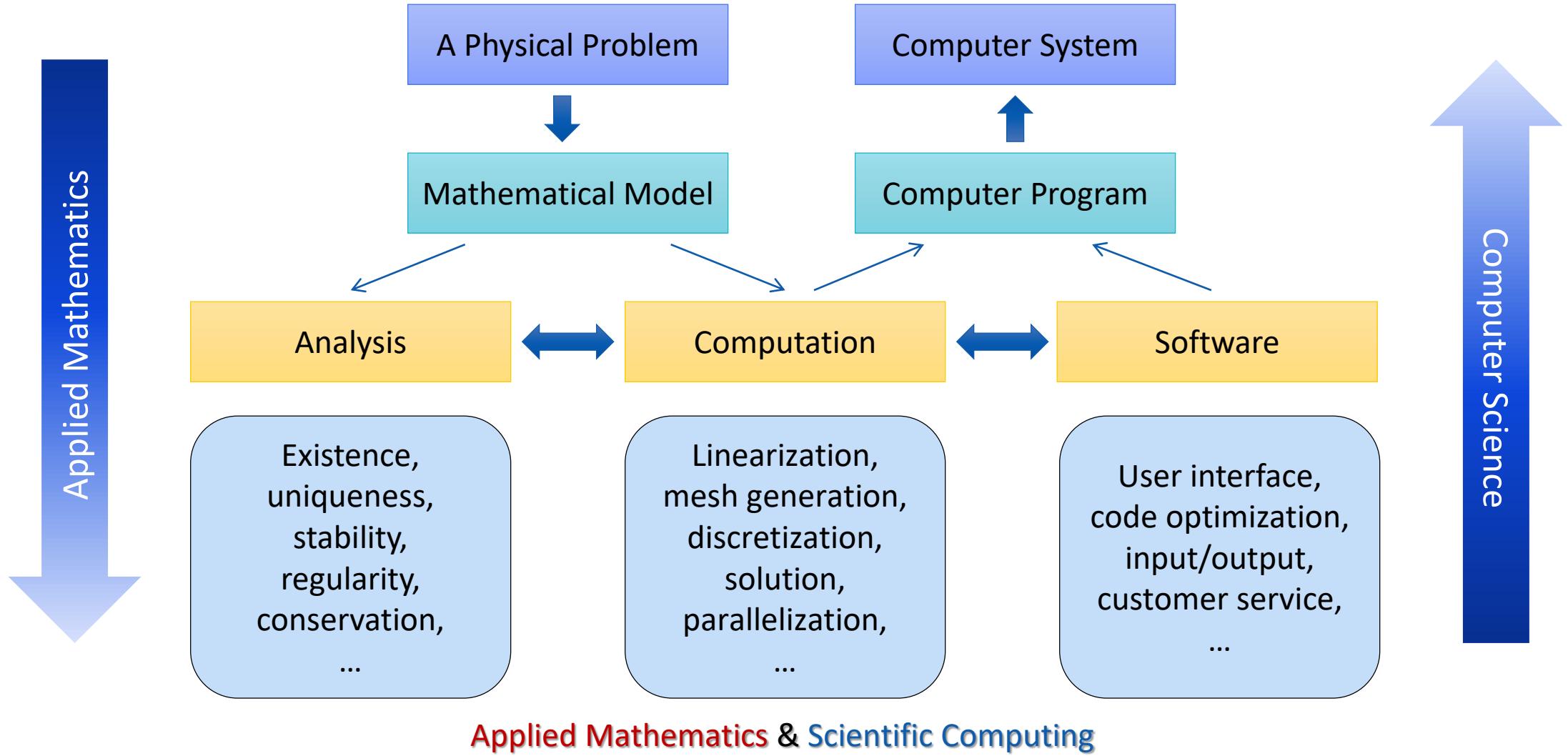
- Too slow
- Too difficult
- Too expensive
- Too dangerous

Simulation ≠ Numerical experiments!



In this lecture, **Solver** := Algebraic Solver (Solution Method / Algorithm / Software)

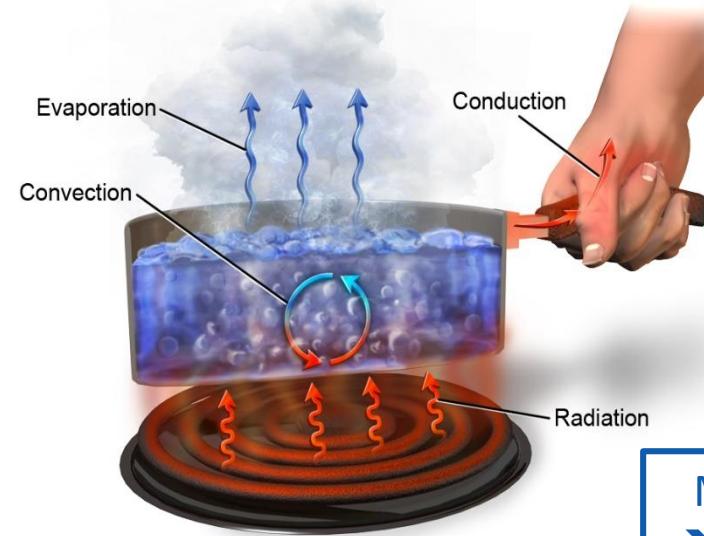
The Third Paradigm of Scientific Discovery



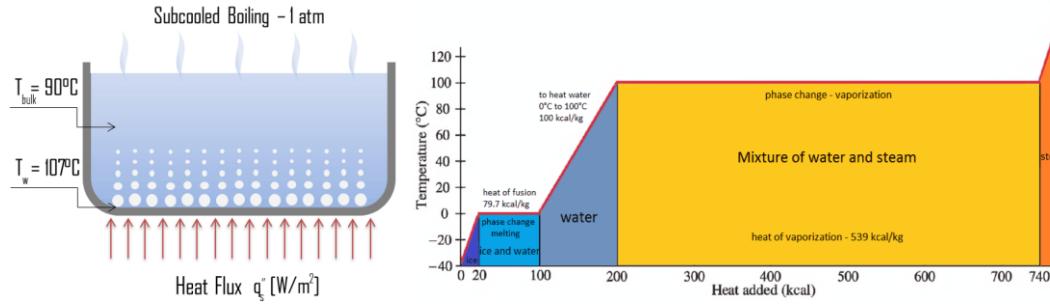
Boiling Water



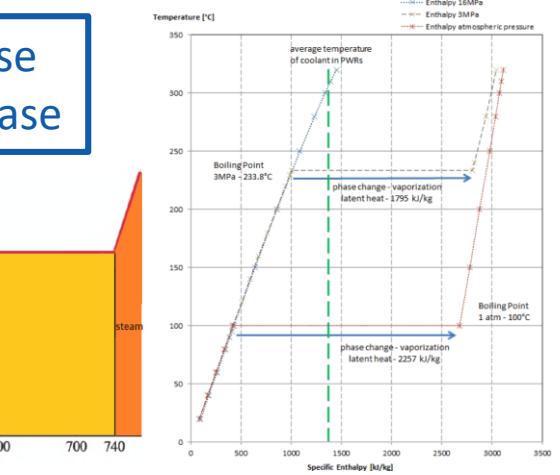
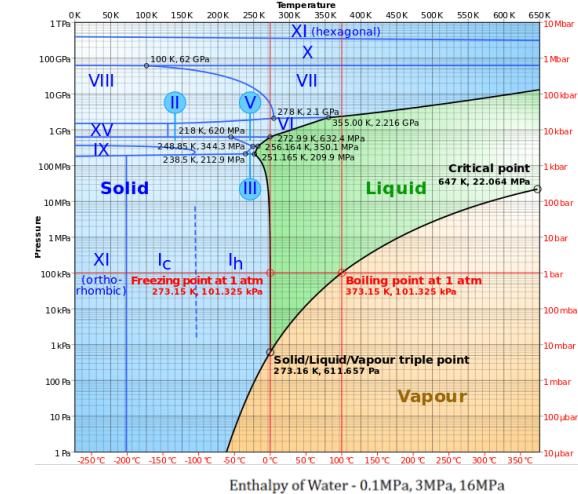
Mechanisms of Heat Transfer



Source: <https://thermttest.com/>



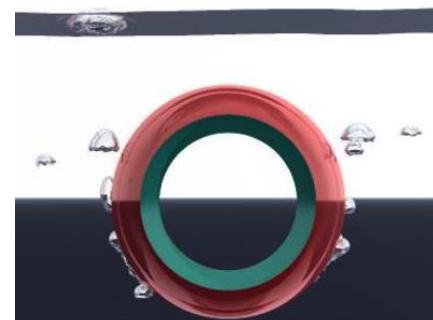
Monophase
→ Multiphase



Source: <https://www.thermal-engineering.org/>

Boiling Some More

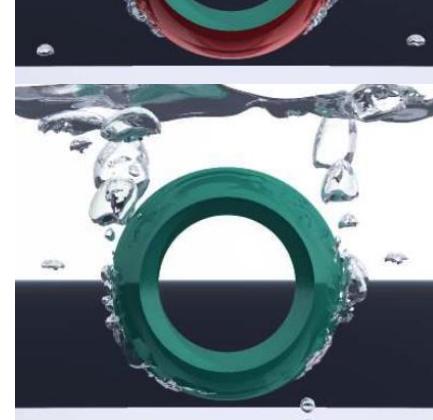
传热



传质



相变



多相流



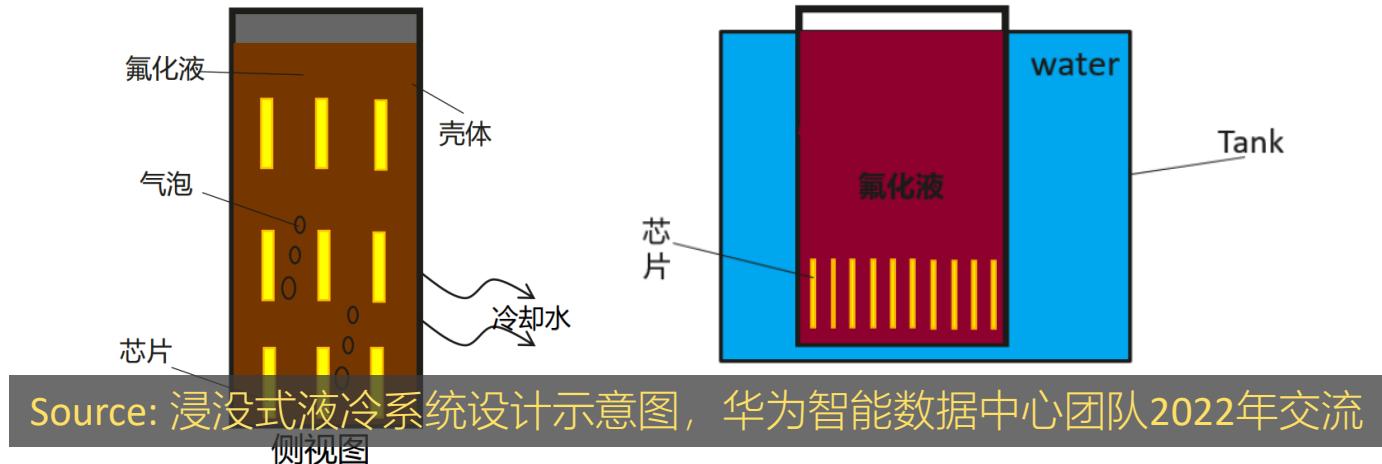
边界层

自由界面

气泡成核

气泡融合

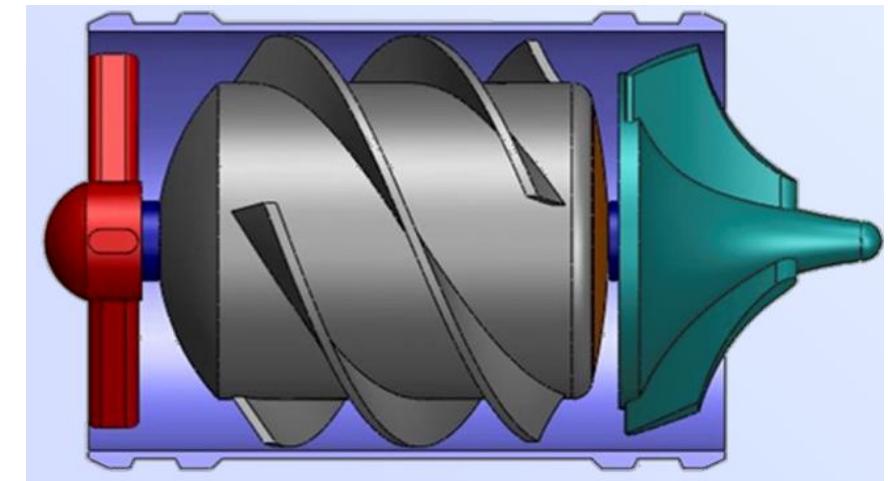
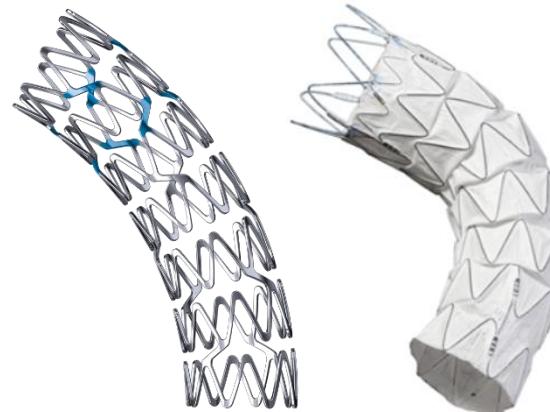
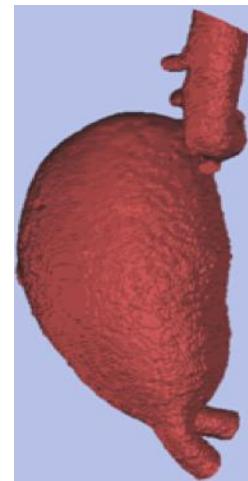
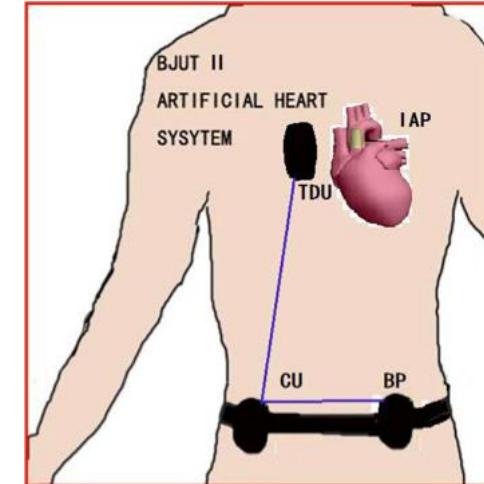
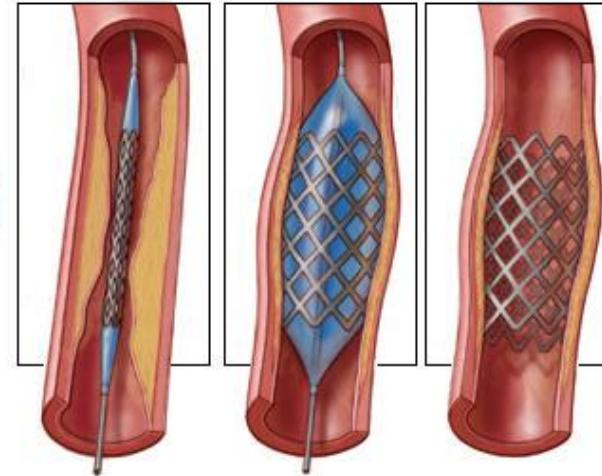
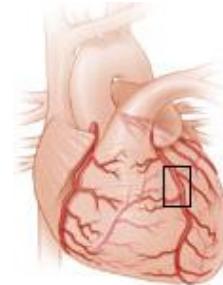
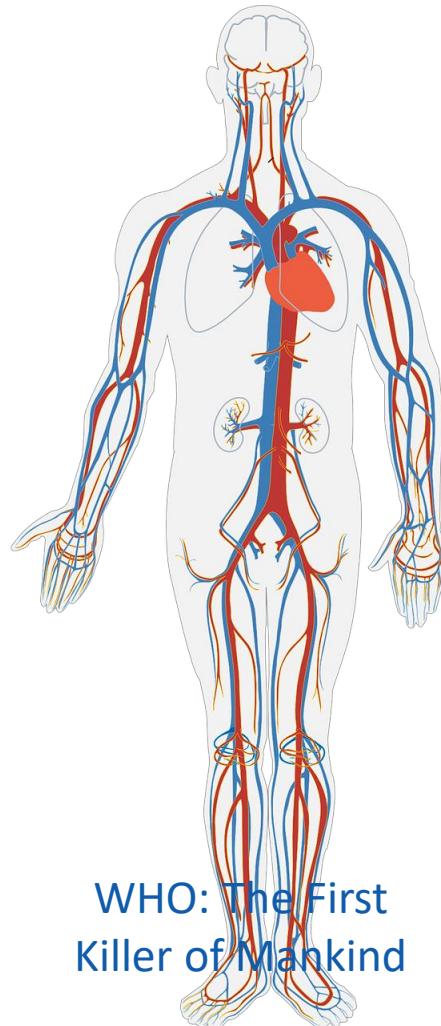
气泡破灭



- 我国数据中心用电量以**每年超10%**的速度递增, 2020年耗电量破2000亿千瓦时, 占全国总电量的**2.71%**
- 冷却系统是数据中心提高能源效率的重点环节, 它所产生的功耗约占数据中心总功耗的**40%**, 有较大的优化空间

Source: Viorel, Unlusu, Metaxas, Sussman, Hussaini. "Physics based boiling simulation", Eurographics/ACM SIGGRAPH Symposium on Computer Animation (2006)

Cardiovascular Diseases (CVDs)

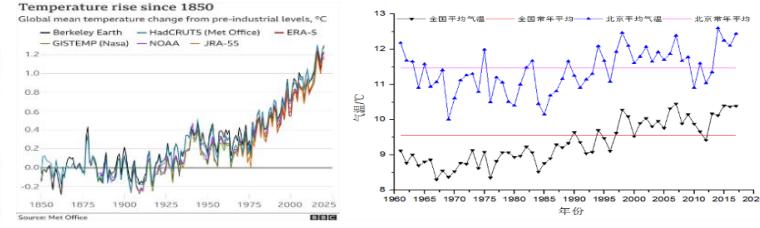
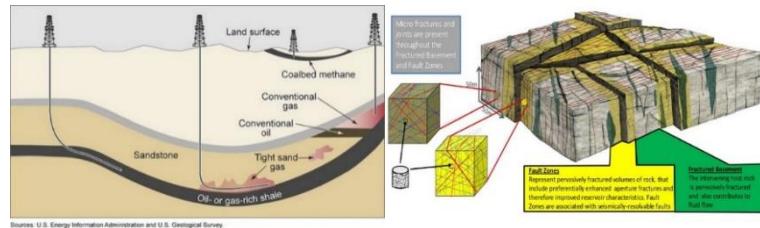
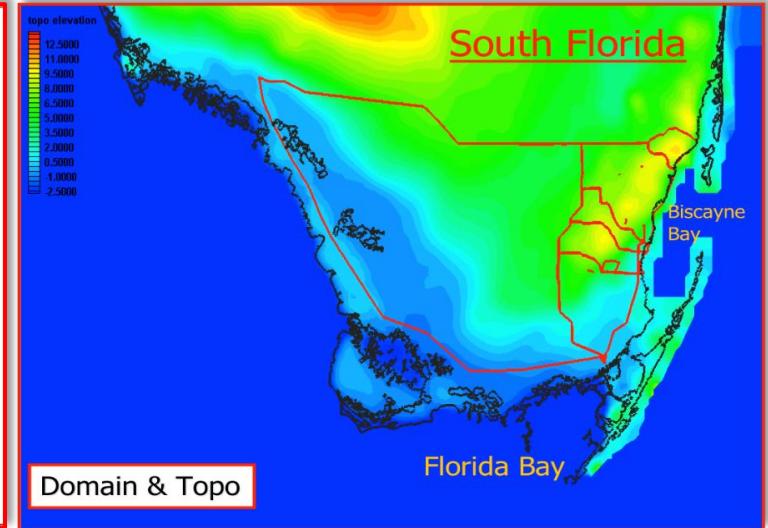
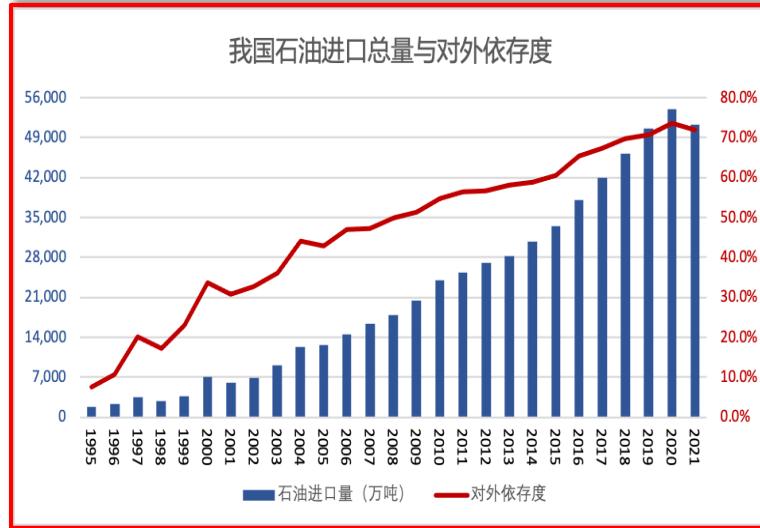


Compositional Flows in Porous Media

能源困局

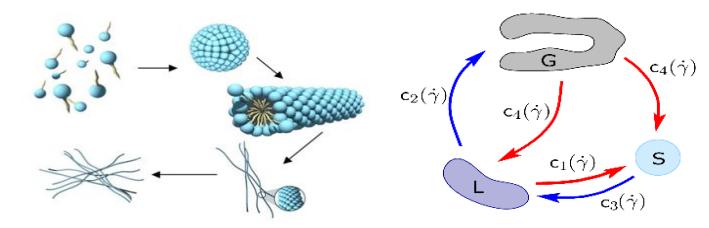
双碳目标

污染治理



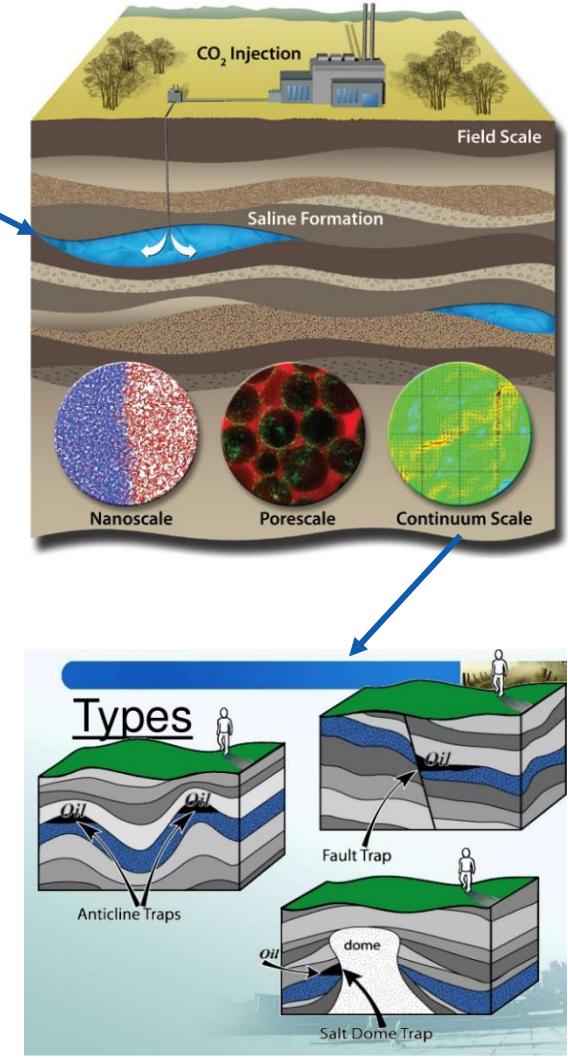
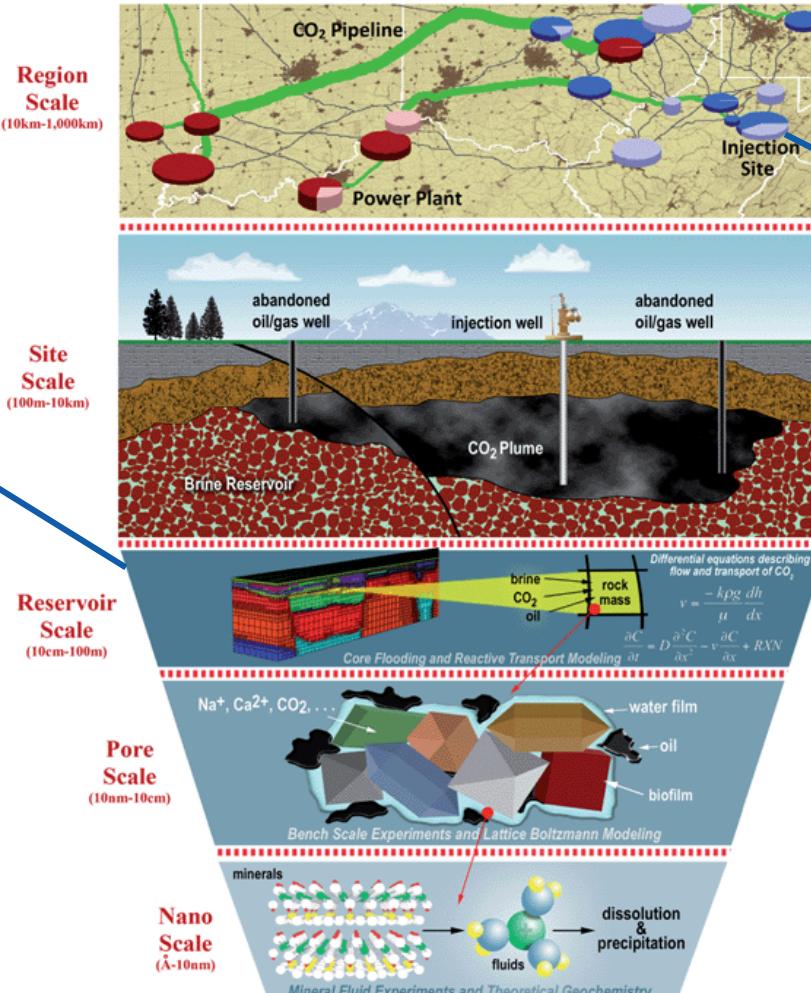
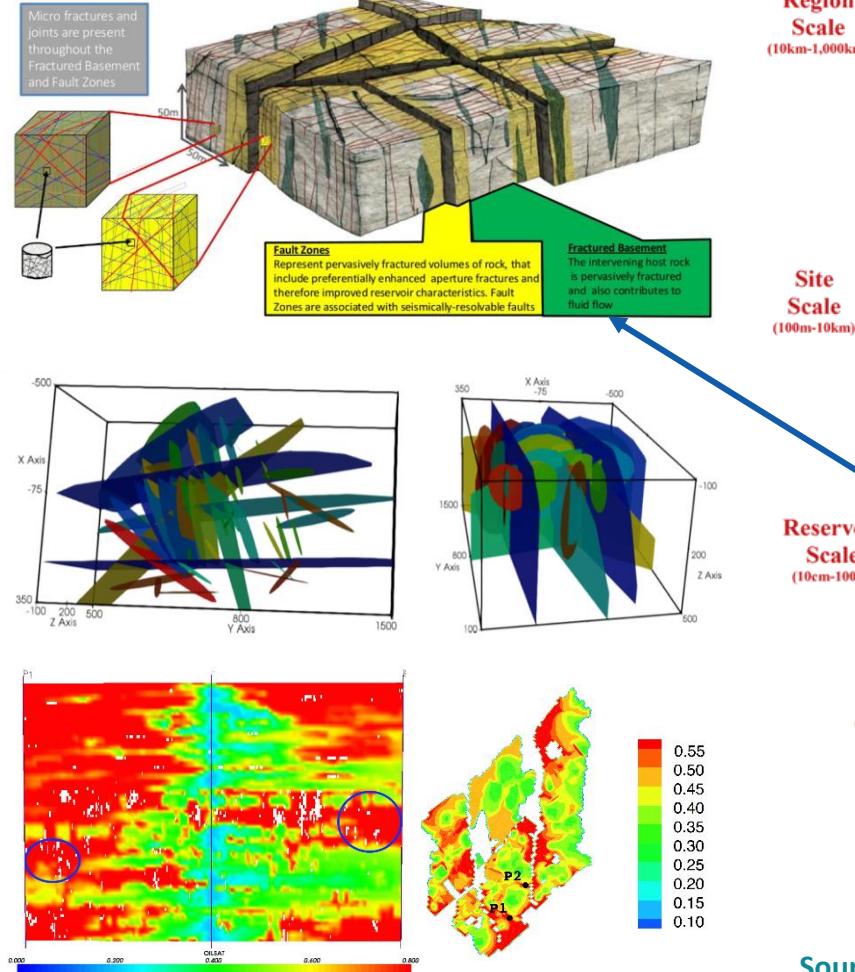
传统油藏、页岩油气、凝析气藏

地热开发、二氧化碳埋存



地下水污染处理、核废料埋存

Petroleum Reservoir Development

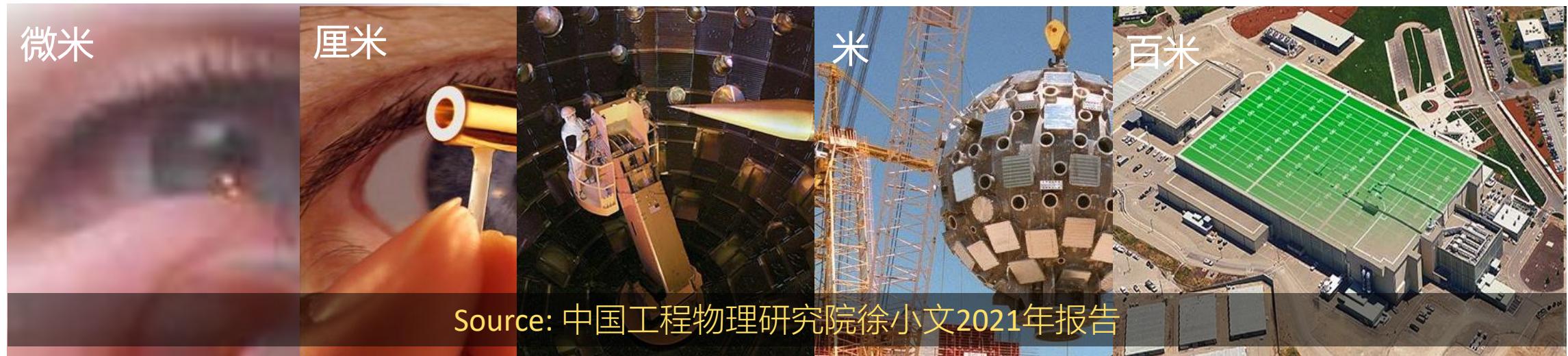


Source: Center for Petroleum & Geosystems Eng, UT Austin

Fusion Energy

美国国家点火装置NIF(National Ignition Facility)于2021年8月8日突破记录，实现了1.35兆焦以上的能量产率，达到了触发它的激光脉冲的能量的70%，成为了最接近“点火”的实验。当核聚变反应产生的能量大于其消耗的能量时，就会发生“点火”现象，燃料可以继续自行“燃烧”，产生的能量超过引发初始反应所需的能量。

- 1994年提出
- 1997年动工
- 2008年建成于LLNL
- 2010年开始实验
- 设计总能量：1.9MJ
- 总投入已超：\$35亿



Some DoE Applications

ExaWind: Turbine Wind Plant Efficiency

Harden wind plant design and layout against energy loss susceptibility; higher penetration of wind energy



Lead: NREL
DOE EERE

ExaAM: Additive Manufacturing of Qualifiable Metal Parts

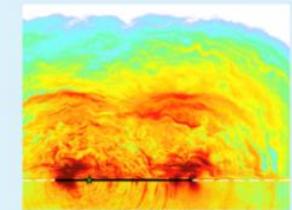
Accelerate the widespread adoption of AM by enabling routine fabrication of qualifiable metal parts



Lead: ORNL
DOE NNSA / EERE

EQSIM: Earthquake Hazard Risk Assessment

Replace conservative and costly earthquake retrofits with safe purpose-fit retrofits and designs

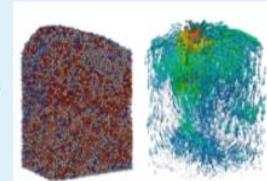


Lead: LBNL
DOE NNSA / NE, EERE

Source: DoE report, <https://www.exascaleproject.org/>

MFIX-Exa: Scale-up of Clean Fossil Fuel Combustion

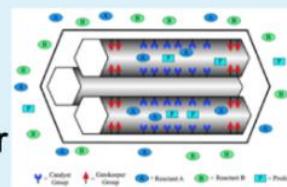
Commercial-scale demo of transformational energy technologies - curbing CO₂ emissions at fossil fuel power plants by 2030



Lead: NETL
DOE EERE

GAMESS: Biofuel Catalyst Design

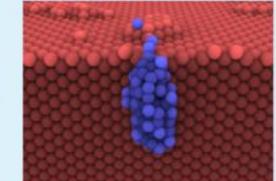
Design more robust and selective catalysts orders of magnitude more efficient at temperatures hundreds of degrees lower



Lead: Ames
DOE BES

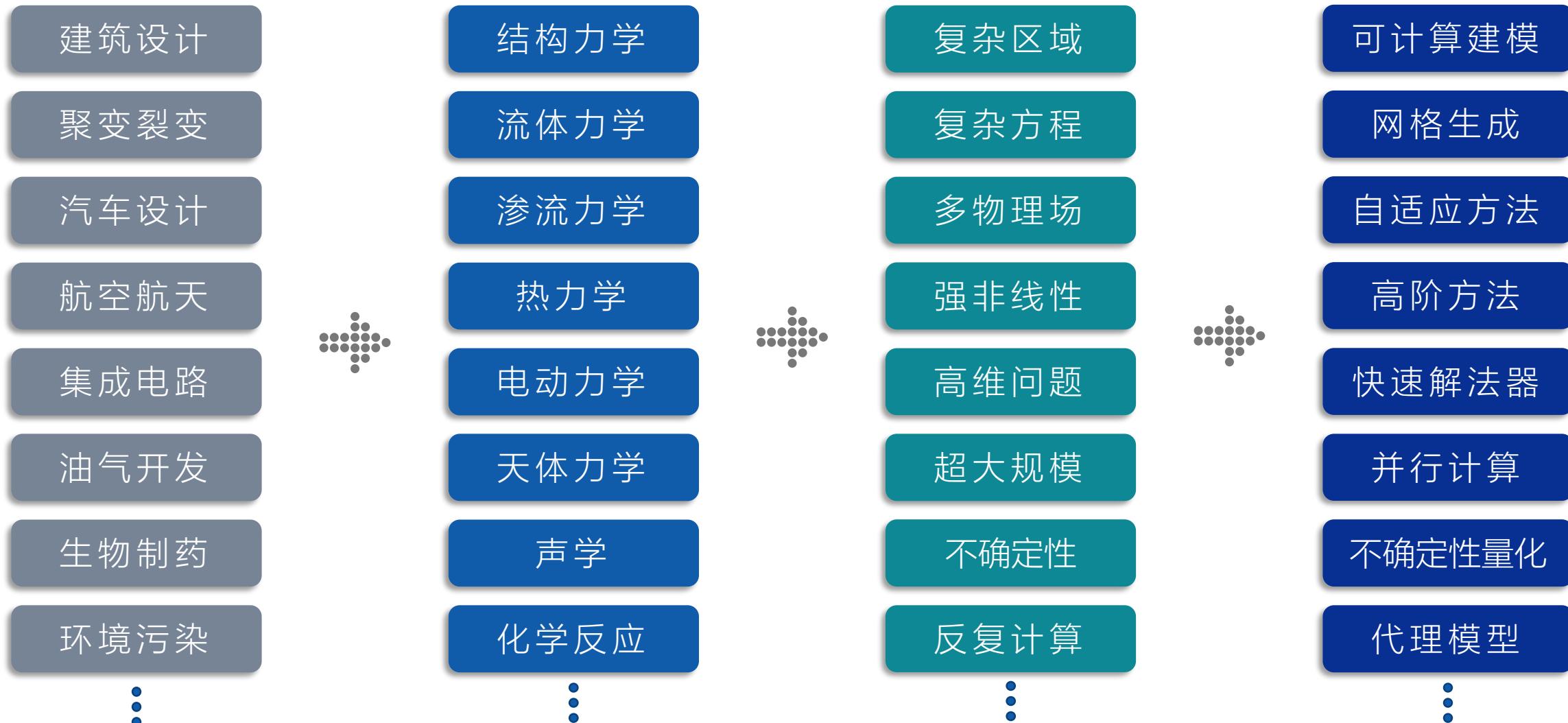
EXAALT: Materials for Extreme Environments

Simultaneously address time, length, and accuracy requirements for predictive microstructural evolution of materials



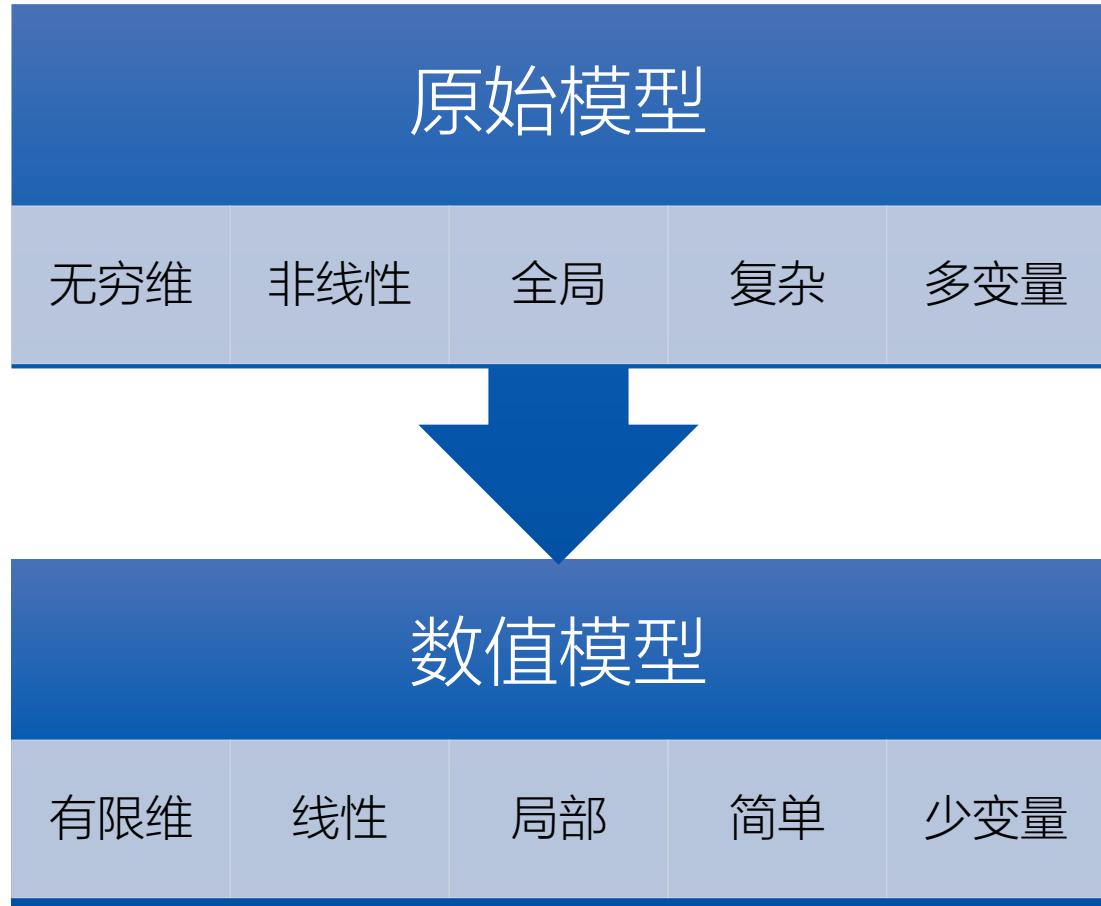
Lead: LANL
DOE BES, FES, NE

Efficient Numerical Simulation



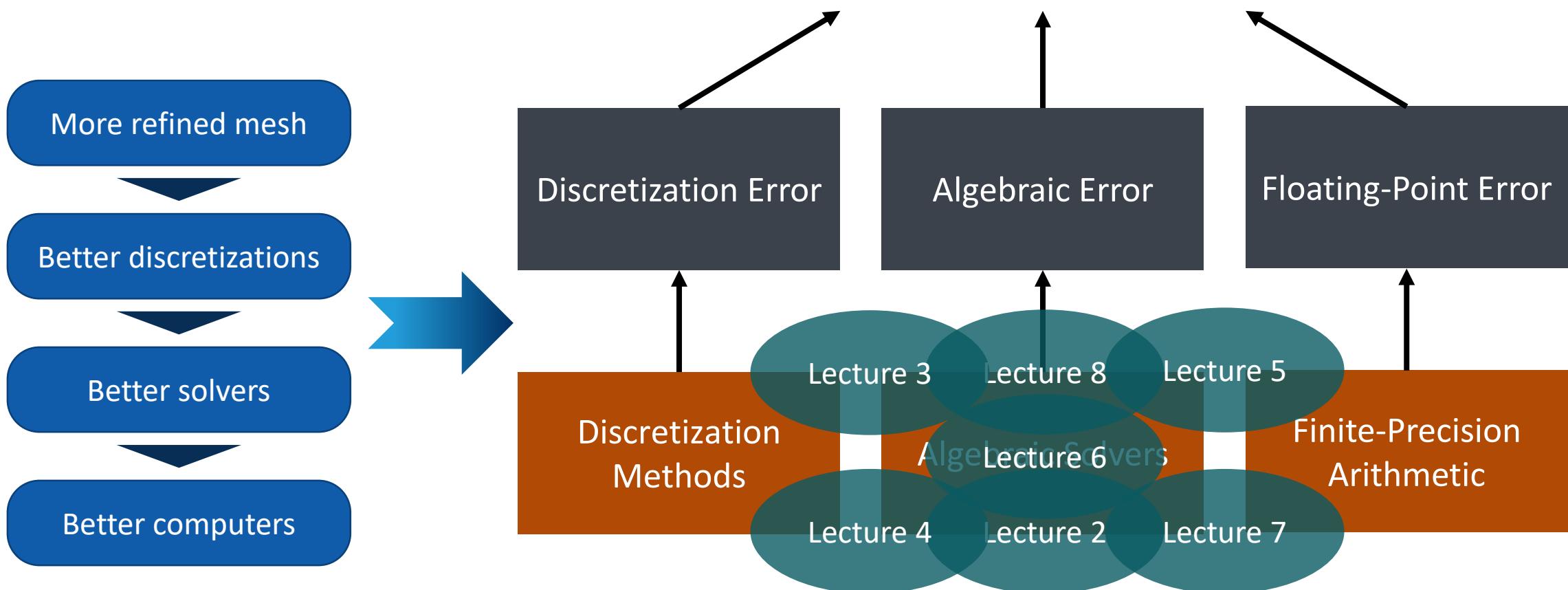
Wisdoms in Numerical Simulation

数值方法设计思路



Sources of Error in Simulation

Approximation: $u(x) = U_h(x) + \mathcal{E}_{\text{dis}} + \mathcal{E}_{\text{alg}} + \mathcal{E}_{\text{fp}}$

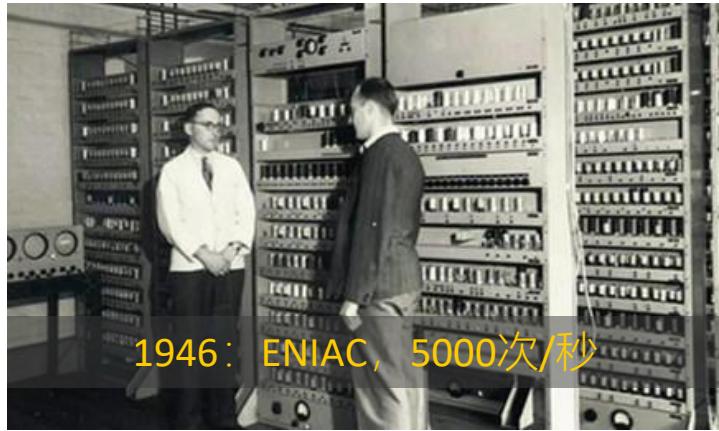


Challenges in Large Simulation

Main difficulties and concerns in large-scale simulation

/02

75 Year, 14 Magnitudes



U.S.		EU	
Sustained ES*: 2022-2023		PEAK ES: 2023-2024	
Peak ES: 2021		Pre-ES: 2021-2022	
Vendors: U.S.		Vendors: Likely European	
Processors: U.S. (some ARM?)		Processors: Likely ARM or RISC-V	
Initiatives: NSCI/ECP		Initiatives: EuroHPC	
Cost: \$600M per system, plus heavy R&D investments		Cost: Over \$350M per system, plus heavy R&D investments	
China		Japan	
Sustained ES*: 2021-2022		Sustained ES*: ~2022	
Peak ES: 2020		Peak ES: Likely as a AI/ML/DL system	
Vendors: Chinese (multiple sites)		Vendors: Japanese	
Processors: Chinese (plus U.S.?)		Processors: Japanese	
13 th Five-Year Plan		1000+ systems, including both 1 system and 100+ systems	
Cost: \$350-\$500M per system, plus heavy R&D		They will also do many smaller size systems	

Source: 中国工程物理研究院徐小文2021年报告

Performance “Walls”



Road To Exascale

- Hardware
- Software
- Applications

	Today's Systems	Predicted Exascale Systems*	Factor Improvement
System Peak	10^{16} flops/s	10^{18} flops/s	100
Node Memory Bandwidth	10^2 GB/s	10^3 GB/s	10
Interconnect Bandwidth	10^1 GB/s	10^2 GB/s	10
Memory Latency	10^{-7} s	$5 \cdot 10^{-8}$ s	2
Interconnect Latency	10^{-6} s	$5 \cdot 10^{-7}$ s	2

*Sources: from P. Beckman (ANL), J. Shalf (LBL), and D. Unat (LBL)

- Memory wall: bandwidth/latency of the channel between CPU and RAM
- Power / energy wall: the chip's overall temperature and power density is high

$$\text{Dynamic Power} = (\text{Activity Factor}) \cdot (\text{Capacitance}) \cdot (\text{Voltage})^2 \cdot (\text{Frequency}) + \text{Power Leakage}$$
- Instruction-level parallelism (ILP) wall: availability of parallel instructions for a processor

Dramatic Architecture Changes for Exascale



Source: 中国工程物理研究院徐小文2019年报告

- 2009-2014：围绕E级计算，DOE组织数十次战略研讨，影响了后续100P/1000P系统的布局以及相关研究计划的部署
- 2015：奥巴马签署国家战略计算规划 (NSCI) 总统令，要求保持美国在超级计算领域的核心竞争力，开始对中国的超算中心实施禁运
- 2016：DOE和NNSA启动百亿亿次计算攻关计划 (ECP)，全面推进百亿亿次“应用-软件-硬件”协同研发，确保2023年左右实现国家战略安全领域的百亿亿次计算能力
- 2019：DOE签订了三台E级机的采购合同（\$18亿硬件研发费用 + \$18亿软件开发费用）

K: infrastructure, culture, portable, reusable, composable, interoperable, reusable

HPC Top500 List 2022.06

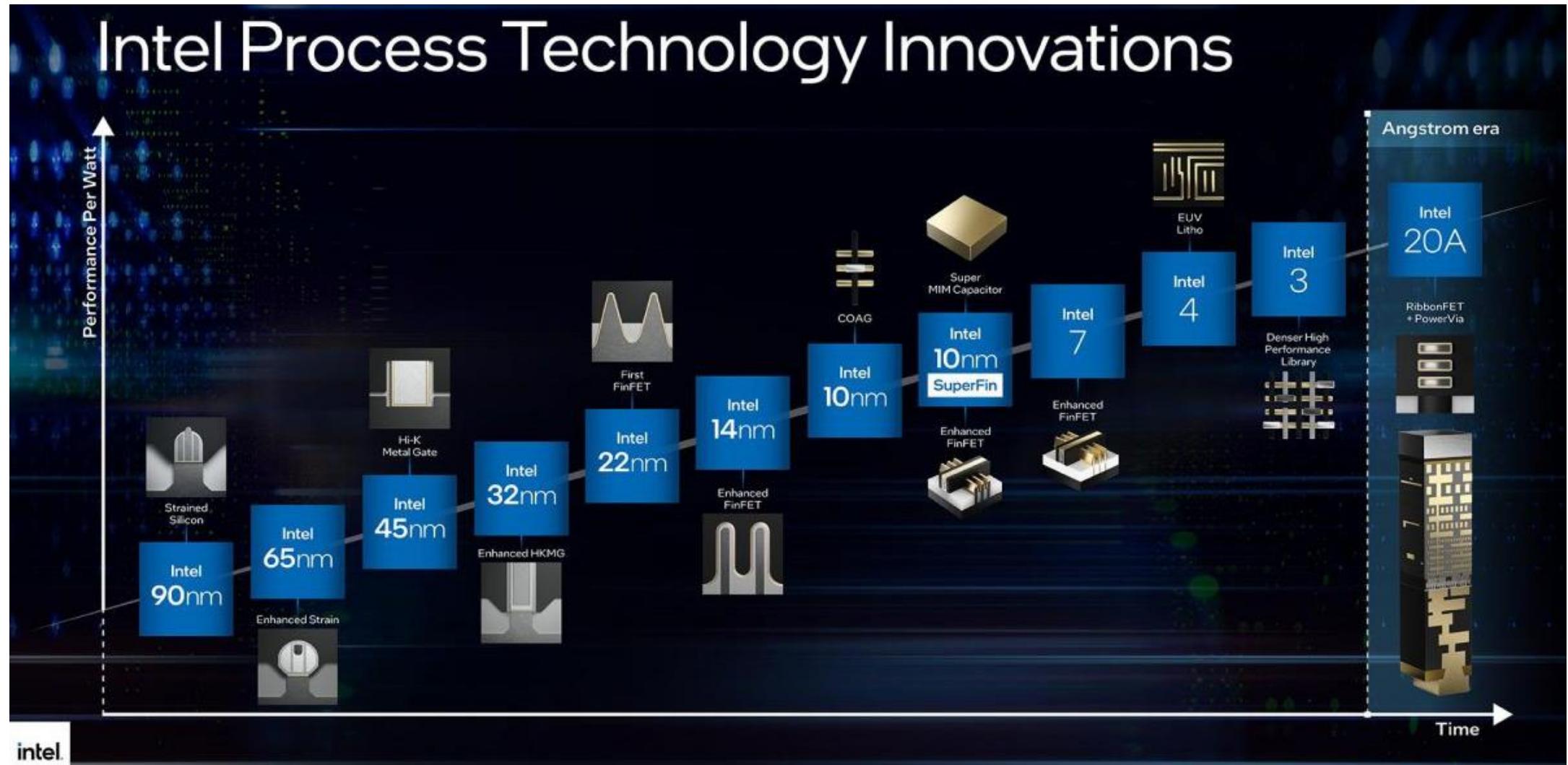


JUNE 2022	SYSTEM	SPECS	SITE	COUNTRY	CORES	R _{MAX} PFLOP/S	POWER MW
1	Frontier	HPE Cray EX235a, AMD Opt 3rd Gen EPYC 64C 2GHz, AMD Instinct MI250X, Slingshot-10	DOE/SC/ORNL	USA	8,730,112	1,102.0	21.3
2	Fugaku	Fujitsu A64FX (48C, 2.2GHz), Tofu Interconnect D	RIKEN R-CCS	Japan	7,630,848	442.0	29.9
3	LUMI	HPE Cray EX235a, AMD Opt 3rd Gen EPYC 64C 2GHz, AMD Instinct MI250X, Slingshot-10	EuroHPC/CSC	Finland	1,268,736	151.9	2.94
4	Summit	IBM POWER9 (22C, 3.07GHz), NVIDIA Volta GV100 (80C), Dual-Rail Mellanox EDR Infiniband	DOE/SC/ORNL	USA	2,414,592	148.6	10.1
5	Sierra	IBM POWER9 (22C, 3.1GHz), NVIDIA Tesla V100 (80C), Dual-Rail Mellanox EDR Infiniband	DOE/NNSA/LLNL	USA	1,572,480	94.6	7.44

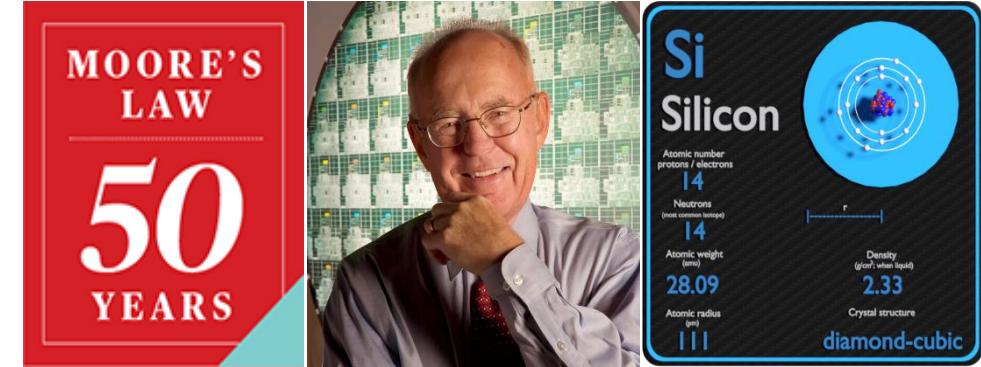
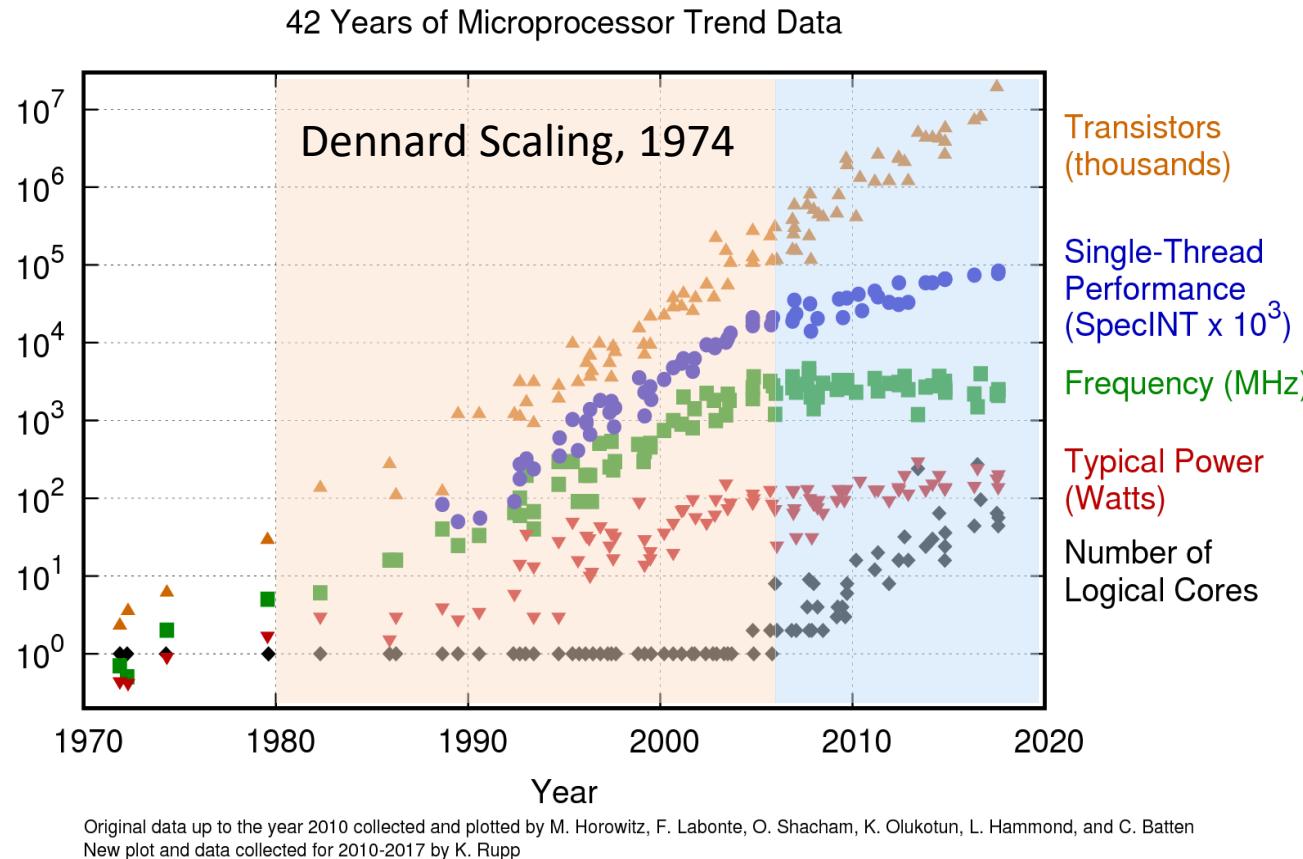


- OK. Fancy!
- A lot of cores!!
- Cost a lot of money!!!
- Can this trend continue?
- Do we need HPC?
- Can we use HPC well?
- How to use HPC well?
- HPL (dense/direct)
- HPCG (sparse/iterative)
- HPL-AI (low precision)
- Green 500 (energy)

Intel® Roadmap



Moore's Law

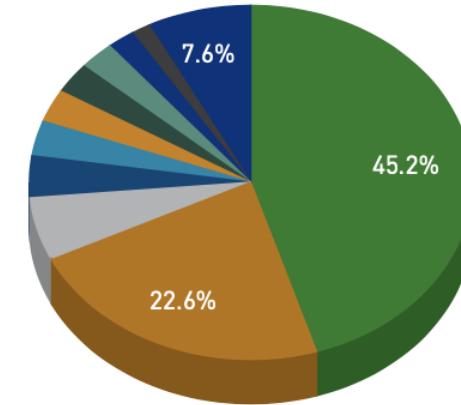


- 由于半导体技术的限制，传统CPU技术路线不能满足需要
- 瓶颈：Power、ILP、latency ...
- 异构多核被广泛采用，芯片开发成本大幅提升
- sub-nano时代？硬件厂商路线图：
2024年20Å, 2040年代2Å

HPC Top500 List 2021.11

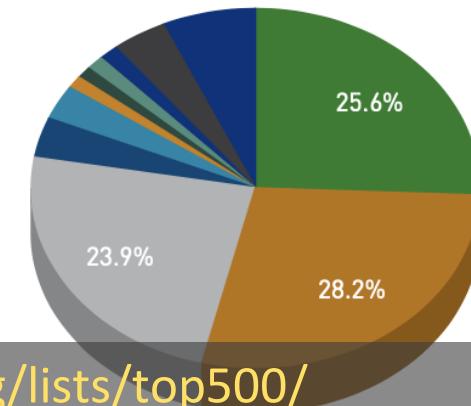
Rank	System	Cores	Rmax (TFlop/s)	Rpeak (TFlop/s)	Power (kW)
1	Supercomputer Fugaku - Supercomputer Fugaku, A64FX 48C 2.2GHz, Tofu interconnect D, Fujitsu RIKEN Center for Computational Science Japan	7,630,848	442,010.0	537,212.0	29,899
2	Summit - IBM Power System AC922, IBM POWER9 22C 3.07GHz, NVIDIA Volta GV100, Dual-rail Mellanox EDR Infiniband, IBM DOE/SC/Oak Ridge National Laboratory United States	2,414,592	148,600.0	200,794.9	10,096
3	Sierra - IBM Power System AC922, IBM POWER9 22C 3.1GHz, NVIDIA Volta GV100, Dual-rail Mellanox EDR Infiniband, IBM / NVIDIA / Mellanox DOE/NNSA/LLNL United States	1,572,480	94,640.0	125,712.0	7,438
4	Sunway TaihuLight - Sunway MPP, Sunway SW26010 260C 1.45GHz, Sunway, NRCPC National Supercomputing Center in Wuxi China	10,649,600	93,014.6	125,435.9	15,371
5	Perlmutter - HPE Cray EX235n, AMD EPYC 7763 64C 2.45GHz, NVIDIA A100 SXM4 40 GB, Slingshot-10, HPE DOE/SC/LBNL/NERSC United States	761,856	70,870.0	93,750.0	2,589

Countries System Share



- China
- United States
- Japan
- France
- Germany
- Netherlands
- Ireland
- Canada
- United Kingdom
- Italy
- Others

Countries Performance Share



- China
- United States
- Japan
- France
- Germany
- Netherlands
- Ireland
- Canada
- United Kingdom
- Italy
- Others

Source: <https://www.top500.org/lists/top500/>

Why Worried

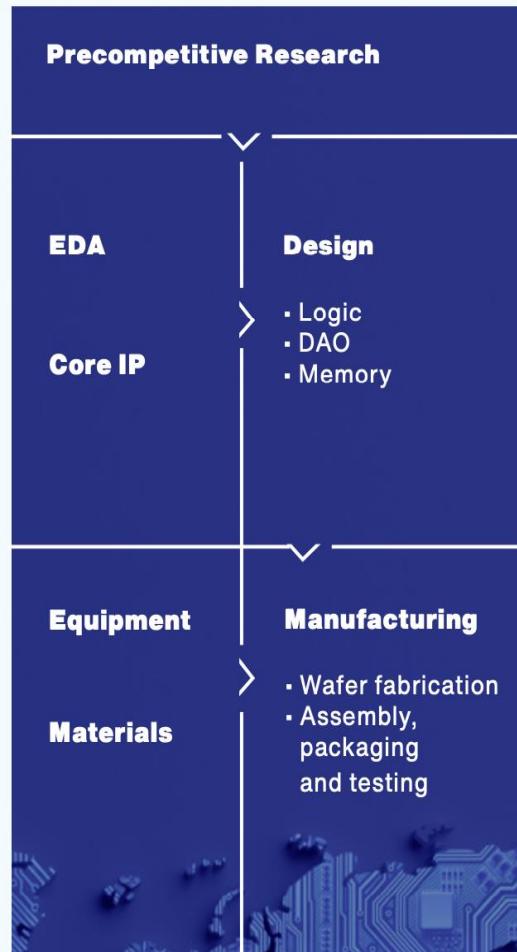


The Wall Street Journal:

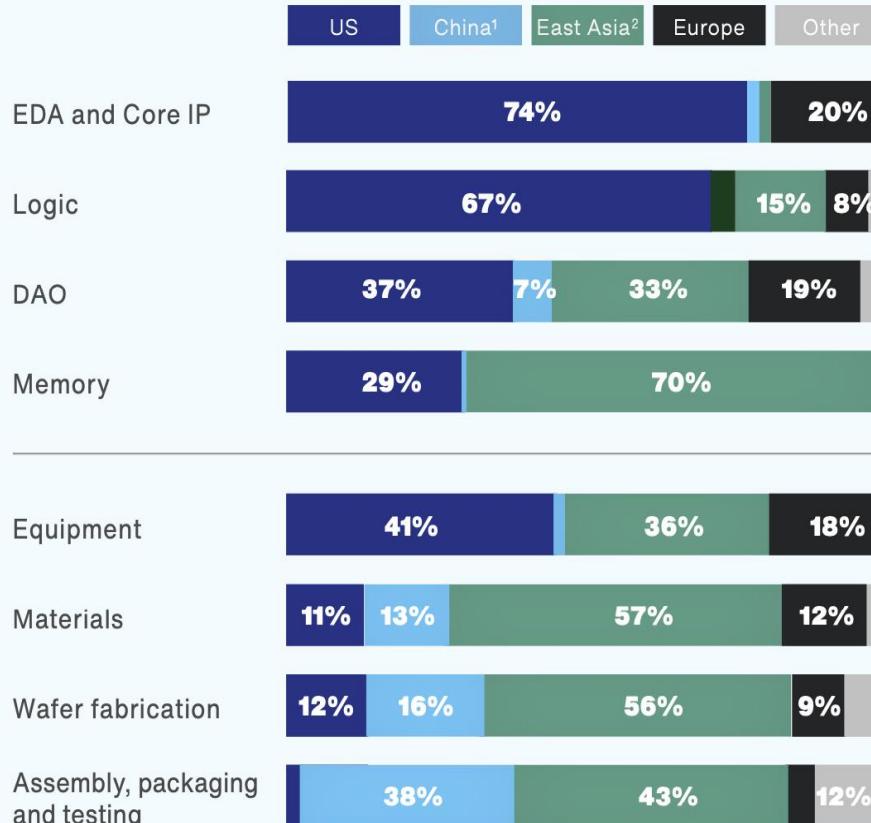
Supercomputing is essential for the development of nuclear weapons, encryption, missile defense and more...

包括BCG在内的很多智库认为：“技术脱钩在很大程度会带来不确定性，并最终损害美国在半导体行业的国际领导地位！”两败俱伤？

Semiconductor Supply Chain



Share by region (% of worldwide total, 2019)



Cost savings vs. fully localized “self-sufficient” supply chains:

\$0.9-1.2T
avoided upfront investment

\$45-125B
annual cost efficiencies

35-65%
enabled reduction in semiconductor prices

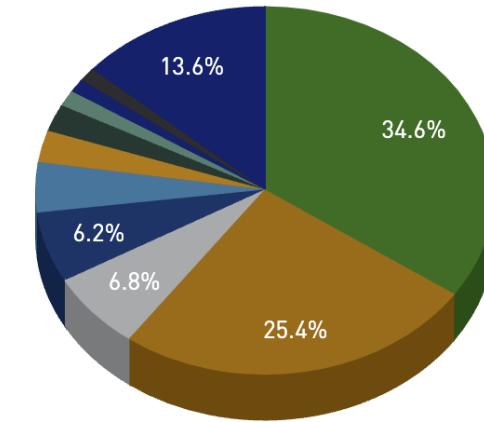
- Key components: Electronic design automation (EDA), core intellectual property (IP), chip design, advanced manufacturing equipment, ...
- China is a leader in assembly, packaging, and testing, which is relatively less skill- and capital-intensive, and is investing aggressively to expand throughout the value chain

Source: BCG + SIA, “Strengthening the Global Semiconductor Supply Chain in an Uncertain Era”, 2021

HPC Top500 List 2022.06

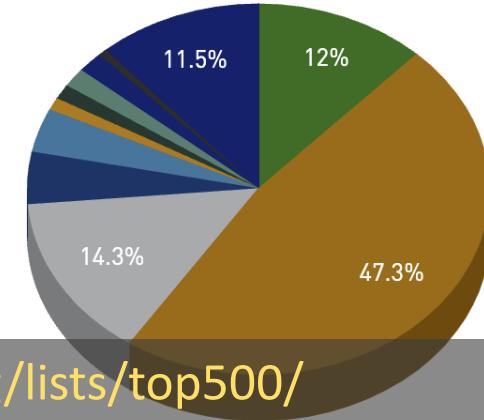
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2	Supercomputer Fugaku - Supercomputer Fugaku, A64FX 48C 2.2GHz, Tofu interconnect D, Fujitsu RIKEN Center for Computational Science Japan	7,630,848	442.01	537.21	29,899
3	LUMI - HPE Cray EX235a, AMD Optimized 3rd Generation EPYC 64C 2GHz, AMD Instinct MI250X, Slingshot-11, HPE EuroHPC/CSC Finland	1,110,144	151.90	214.35	2,942
4	Summit - IBM Power System AC922, IBM POWER9 22C 3.07GHz, NVIDIA Volta GV100, Dual-rail Mellanox EDR Infiniband, IBM DOE/SC/Oak Ridge National Laboratory United States	2,414,592	148.60	200.79	10,096
5	Sierra - IBM Power System AC922, IBM POWER9 22C 3.1GHz, NVIDIA Volta GV100, Dual-rail Mellanox EDR Infiniband, IBM / NVIDIA / Mellanox DOE/NNSA/LLNL United States	1,572,480	94.64	125.71	7,438

Countries System Share



- China
- United States
- Japan
- Germany
- France
- Canada
- United Kingdom
- Russia
- Italy
- Netherlands
- Others

Countries Performance Share



- China
- United States
- Japan
- Germany
- France
- Canada
- United Kingdom
- Russia
- Italy
- Netherlands
- Others

Source: <https://www.top500.org/lists/top500/>

HPCG and Green500

Rank	Site	Computer	Cores	HPL Rmax (Pflop/s)	TOP500 Rank	HPCG (Pflop/s)	Fraction of Peak
1	RIKEN Center for Computational Science Japan	Supercomputer Fugaku — A64FX 48C 2.2GHz, Tofu interconnect D	7,630,848	442.01	2	16.00	3.0%
2	DOE/SC/Oak Ridge National Laboratory United States	Summit — IBM POWER9 22C 3.07GHz, Dual-rail Mellanox EDR Infiniband, NVIDIA Volta GV100	2,414,592	148.60	4	2.926	1.5%
3	EuroHPC/CSC Finland	LUMI — AMD Optimized 3rd Generation EPYC 64C 2GHz, Slingshot-11, AMD Instinct MI250X	1,110,144	151.90	3	1.936	0.9%
4	DOE/SC/LBNL/NERSC United States	Perlmutter — AMD EPYC 7763 64C 2.45GHz, Slingshot-10, NVIDIA A100 SXM4 40 GB	761,856	70.87	7	1.905	2.0%
5	DOE/NNSA/LLNL United States	Sierra — IBM POWER9 22C 3.1GHz, Dual-rail Mellanox EDR Infiniband, NVIDIA Volta GV100	1,572,480	94.64	5	1.796	1.4%
6	NVIDIA Corporation United States	Selene — AMD EPYC 7742 64C 2.25GHz, Mellanox HDR Infiniband, NVIDIA A100	555,520	63.46	8	1.623	2.0%
7	Forschungszentrum Juelich (FZJ) Germany	JUWELS Booster Module — AMD EPYC 7402 24C 2.8GHz, Mellanox HDR InfiniBand/ParTec ParaStation ClusterSuite, NVIDIA A100	449,280	44.12	11	1.275	1.8%
8	Saudi Aramco Saudi Arabia	Dammam-7 — Xeon Gold 6248 20C 2.5GHz, InfiniBand HDR 100, NVIDIA Tesla V100 SXM2	672,520	22.40	18	0.881	1.6%
9	Eni S.p.A. Italy	HPC5 — Xeon Gold 6252 24C 2.1GHz, Mellanox HDR Infiniband, NVIDIA Tesla V100	669,760	35.45	12	0.860	1.7%
10	Information Technology Center, The University of Tokyo Japan	Victoria (BDIIC-01) (Cray EX) — A64FX 48C 2.2GHz, Tofu interconnect D	368,640	22.12	20	0.818	3.2%

Rank	TOP500 Rank	System	Cores	Rmax (PFlop/s)	Power (kW)	Energy Efficiency (GFlops/watts)
1	29	Frontier TDS - HPE Cray EX235a, AMD Optimized 3rd Generation EPYC 64C 2GHz, AMD Instinct MI250X, Slingshot-11, HPE DOE/SC/Oak Ridge National Laboratory United States	120,832	19.20	309	62.684
2	1	Frontier - HPE Cray EX235a, AMD Optimized 3rd Generation EPYC 64C 2GHz, AMD Instinct MI250X, Slingshot-11, HPE DOE/SC/Oak Ridge National Laboratory United States	8,730,112	1,102.00	21,100	52.227
3	3	LUMI - HPE Cray EX235a, AMD Optimized 3rd Generation EPYC 64C 2GHz, AMD Instinct MI250X, Slingshot-11, HPE EuroHPC/CSC Finland	1,110,144	151.90	2,942	51.629
4	10	Adastra - HPE Cray EX235a, AMD Optimized 3rd Generation EPYC 64C 2GHz, AMD Instinct MI250X, Slingshot-11, HPE Grand Equipement National de Calcul Intensif - Centre Informatique National de l'Enseignement Suprieur (GENCI-CINES) France	319,072	46.10	921	50.028
5	326	MN-3 - MN-Core Server, Xeon Platinum 8260M 24C 2.4GHz, Preferred Networks MN-Core, MN-Core DirectConnect, Preferred Networks Preferred Networks	1,664	2.18	53	40.901

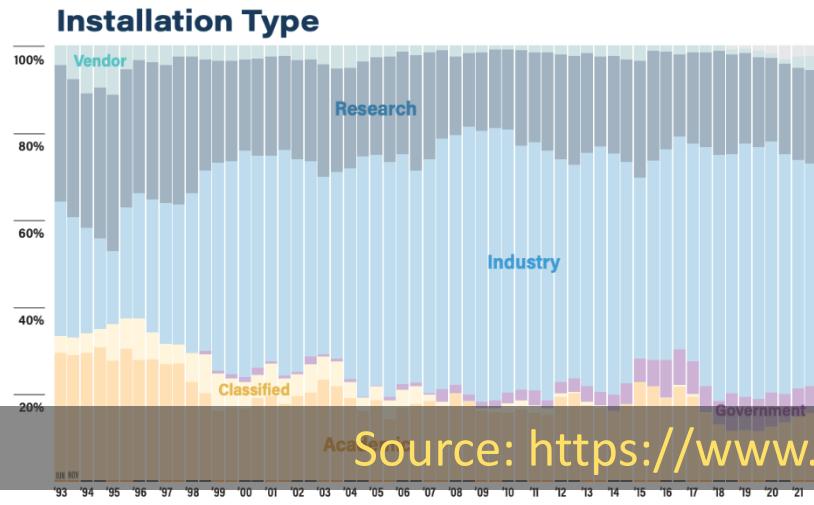
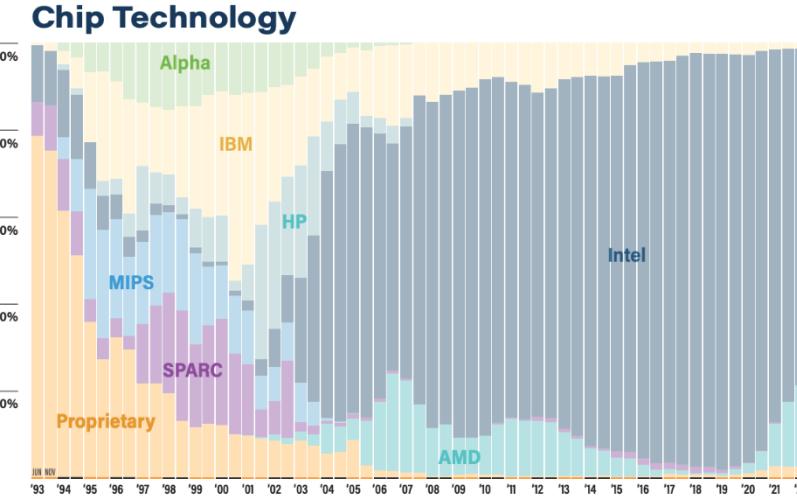
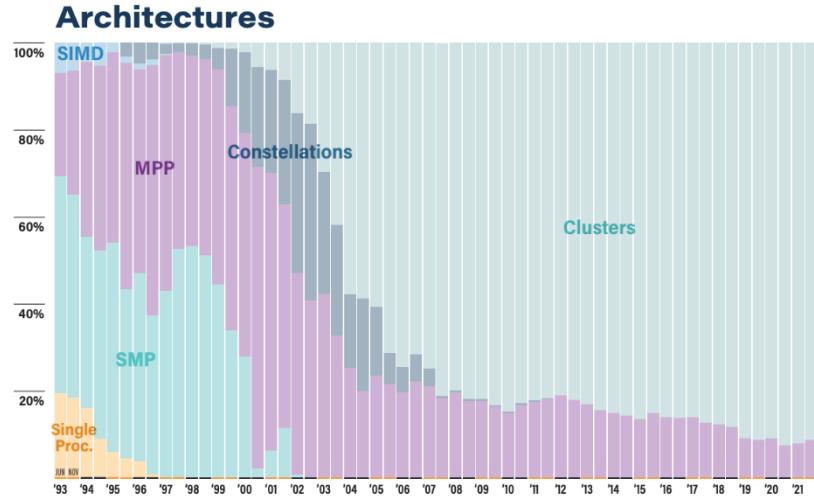
<http://hpcg-benchmark.org/>

<https://www.top500.org/lists/green500/>

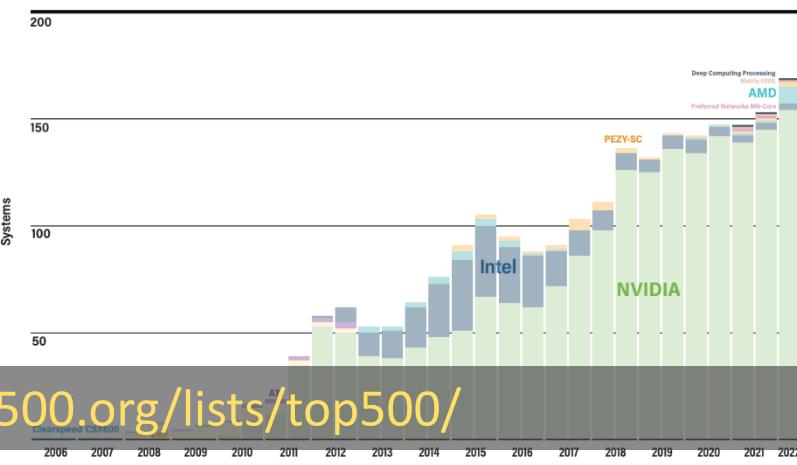
Rank	Site	Computer	Cores	HPL-AI (Eflop/s)	TOP500 Rank	HPL Rmax (Eflop/s)	Speedup
1	DOE/SC/ORNL, USA	Frontier	8,730,112	6.861	1	1.102	6.2
2	RIKEN, Japan	Fugaku	7,630,848	2.000	2	0.4420	4.5
3	DOE/SC/ORNL, USA	Summit	2,414,592	1.411	4	0.1486	9.5
4	NVIDIA, USA	Selene	555,520	0.630	8	0.0630	9.9
5	DOE/SC/LBNL, USA	Perlmutter	761,856	0.590	7	0.0709	8.3
6	FZJ, Germany	JUWELS BM	449,280	0.470	11	0.0440	10.0
7	University of Florida, USA	HiPerGator	138,880	0.170	34	0.0170	9.9
8	SberCloud, Russia	Christofari Neo	98,208	0.123	47	0.0120	10.3
9	DOE/SC/ANL, USA	Polaris	259,840	0.114	14	0.0238	4.8
10	ITC, Japan	Wisteria	368,640	0.100	20	0.0220	4.5
11	NSC, Sweden	Berzelius	59,520	0.052	103	0.0053	9.5
12	Cyfronet, Poland	Athena	47,616	0.050	103	0.0051	10.1
13	Nagoya, Japan	Flow Type I	110,592	0.030	82	0.0066	4.5
14	NVIDIA, USA	Tethys	19,840	0.024	320	0.0023	10.8
15	NVIDIA, USA	DGX Saturn V	87,040	0.022	128	0.0040	5.5
16	CloudMTS, Russia	MTS GROM	19,840	0.015	319	0.0023	6.6
17	Calcul Quebec/Compute Canada	Narval	76,320	0.014	93	0.0059	2.4
18	DOE/SC/ANL, USA	ThetaGPU	280,320	0.012	79	0.0069	1.7
19	Indiana University, USA	Big Red 200 GPU	51,744	0.006	160	0.0026	2.4
20	Texas A&M University, USA	Grace GPU	26,400	0.004	366	0.0021	1.7

<https://hpl-ai.org/>

Some Statistics on Architectures

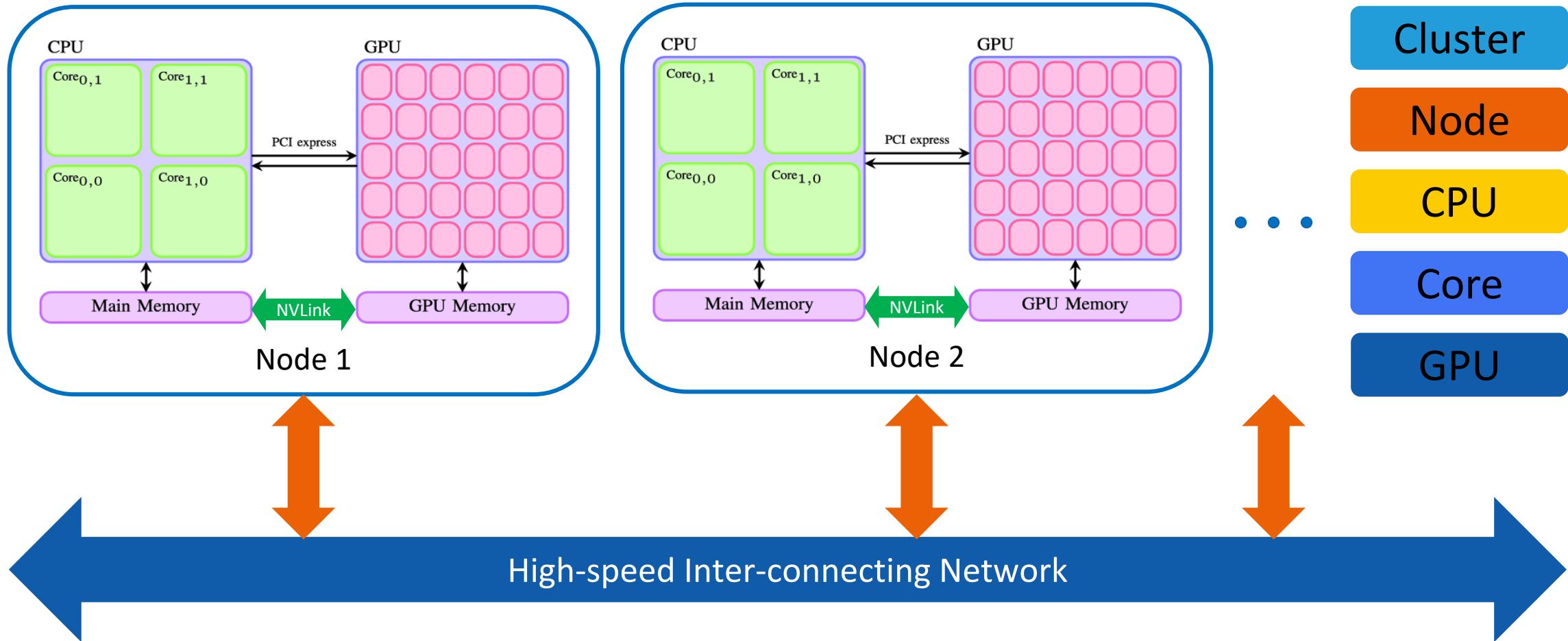


Source: <https://www.top500.org/lists/top500/>



- GPUs and other accelerators are more and more popular
- nVidia® dominates the HPC accelerator market
- Reasons:
 - Hardware
 - Software
 - Community

Heterogenous Cluster Architecture



算法的复杂度和可扩展性、对多核CPU的利用率、对众核加速卡的利用率、数据传输时间.....

Fast Algebraic Solvers

How to develop faster and/or better solvers?

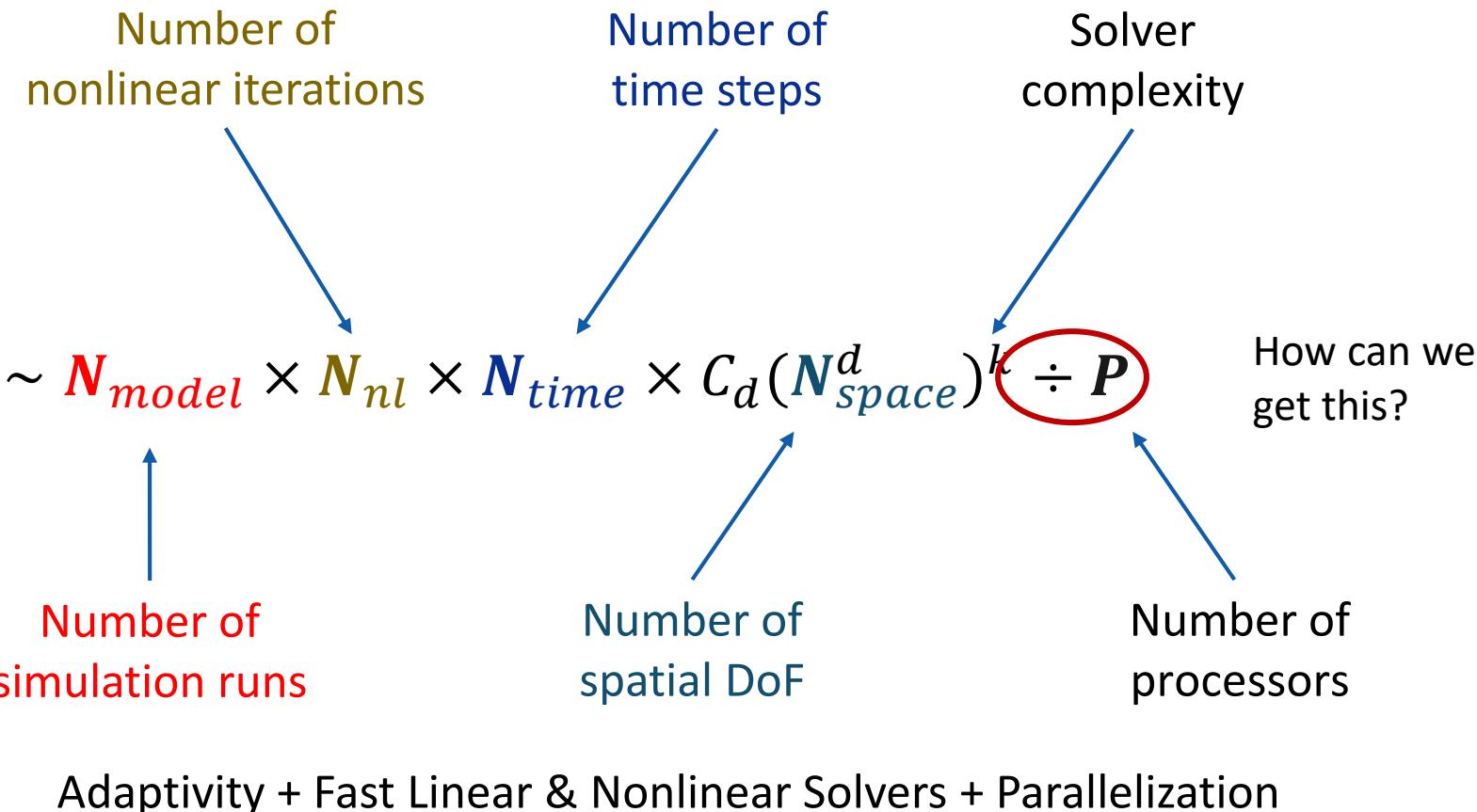
/03

Computational Complexity

Linearization → time marching → spatial discretization → linear solver → parallelization

Q: What prevents us from achieving better performance?

Q: Complexity is not wall-time! What else should we consider for real performance?



Make Good Use of Supercomputers

SUNWAY TAIHULIGHT - SUNWAY MPP, SUNWAY SW26010
260C 1.45GHZ, SUNWAY

Site:	National Supercomputing Center in Wuxi
Manufacturer:	NRCPC
Cores:	10,649,600
Memory:	1,310,720 GB
Processor:	Sunway SW26010 260C 1.45GHz
Interconnect:	Sunway
Performance	
Linpack Performance (Rmax)	93,014.6 TFlop/s
Theoretical Peak (Rpeak)	125,436 TFlop/s
Nmax	12,288,000
HPCG [TFlop/s]	480.848
Power Consumption	
Power:	15,371.00 kW (Submitted)
Power Measurement Level:	2
Source: https://www.top500.org/lists/top500/	
Operating System:	Sunway RaiseOS 2.0.5



- Power assumption = **15MW**
- Peak performance Rpeak = **125PFlops**
- HPL performance Rmax = **74%**
- **HPCG performance = 0.38%**

An Illustration of Parallel Computing

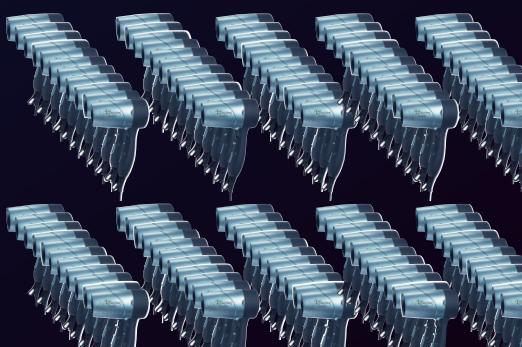
What's the problem?

replacing 4 strong jet engines



Would you want to propel
a Super Jumbo

with 300,000
blow dryer fans?



空客A380发动机的推力约为300千牛，最大速度300米/秒，功率为90000千瓦，这大致相当于300,000台普通家用吹风机的功率，但你能用吹风机驱动A380吗？这可行吗？如果可行，带来什么变化？现在，想象一下你有1000万台不同功率的吹风机！

Ulrich Rüde, [Friedrich-Alexander-University of Erlangen-Nürnberg, Erlangen, Germany](#)

Sequential vs Parallel Algorithms

管理

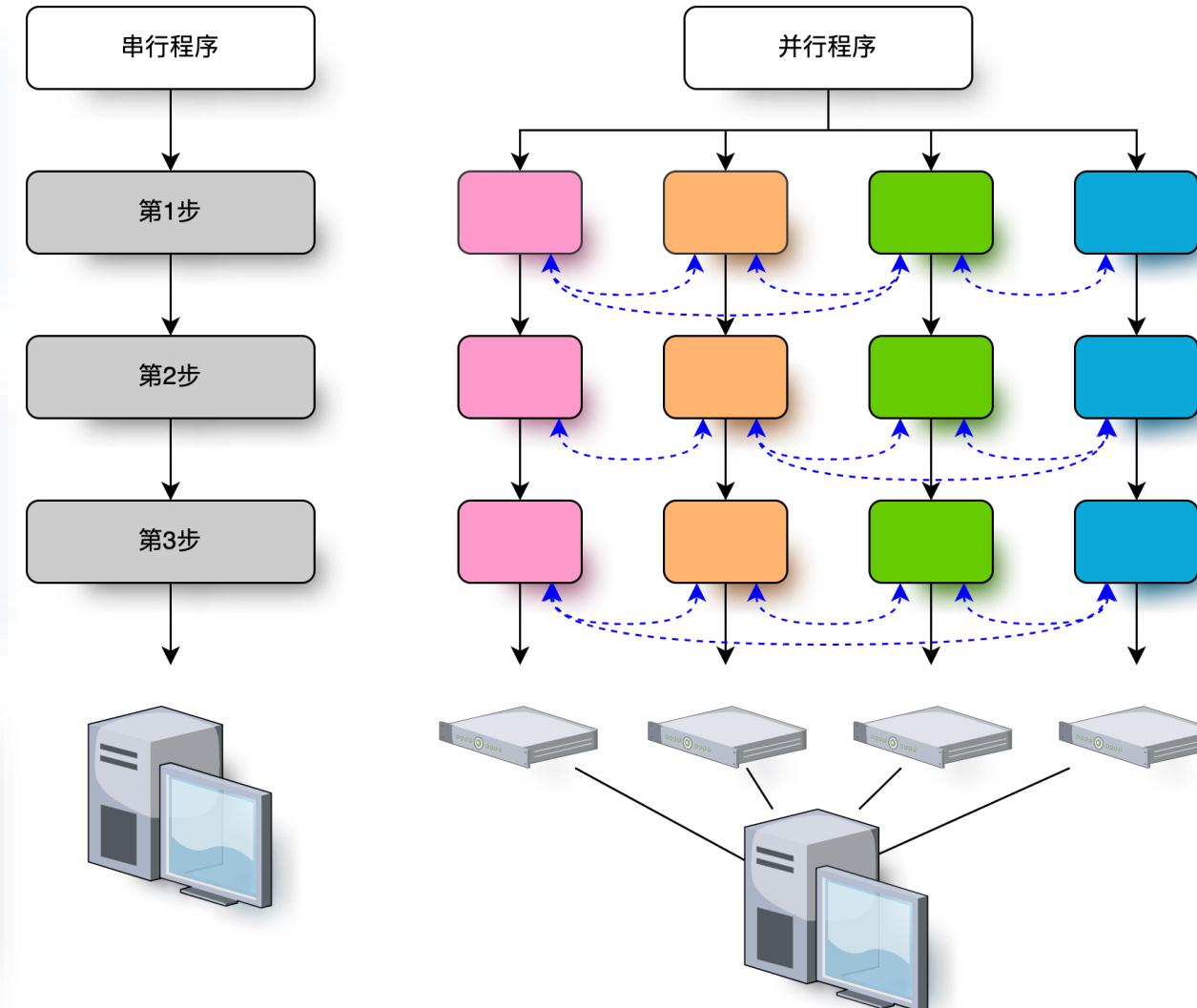
把任务分配给
每个进程，让
大家都有事干

人事

减少进程之间
交流的次数和
开销

流程

减少数据之间
的依赖关系和
相互等待



为了实现整体的效率和资源利用率的最大化，可能会牺牲个人甚至每个人的利益。对应的串行算法不一定快！甚至不收敛，例如：Jacobi 和GS方法。

How to Measure Parallel Efficiency

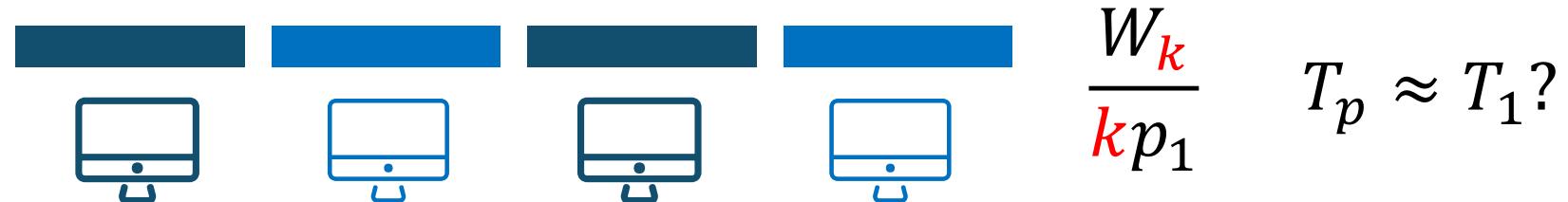
- 强可扩展性



若需要解决一个任务，把计算资源增大到原来的 k 倍，能加速 k 倍吗？

定义并行效率 $E = S/k$ ，我们希望是100%！

- 弱可扩展性



若需要解决 k 倍大的任务，计算资源同比例增加，能保持相同耗时吗？

为了效率保持不变，需要多大的问题规模？

Three Mountains on Parallel Simulation

Amdahl's Law 1967



如果串行部分占总时间的10%，那并行加速比不可能超过10倍

对于大规模系统来说，很多应用程序的强可扩展性是难以实现的！

对于很多应用来说，更需要的是计算越来越大规模的问题！需要是弱可扩展性，而不是强可扩展性

Gustafson-Barsis's Law 1988



当问题规模与计算资源同比例增大 S 倍时，加速比最高就可达 $0.9S+0.1$

Gabriel Wittum: HPC Paradox



当购买了大10倍的硬件系统，希望能更快地求解大10倍的问题；但现实很残酷，必须有最优算法才可以！

最优算法对于充分发挥HPC效率及实现弱可扩展性至关重要！

硬件投资



并行效率



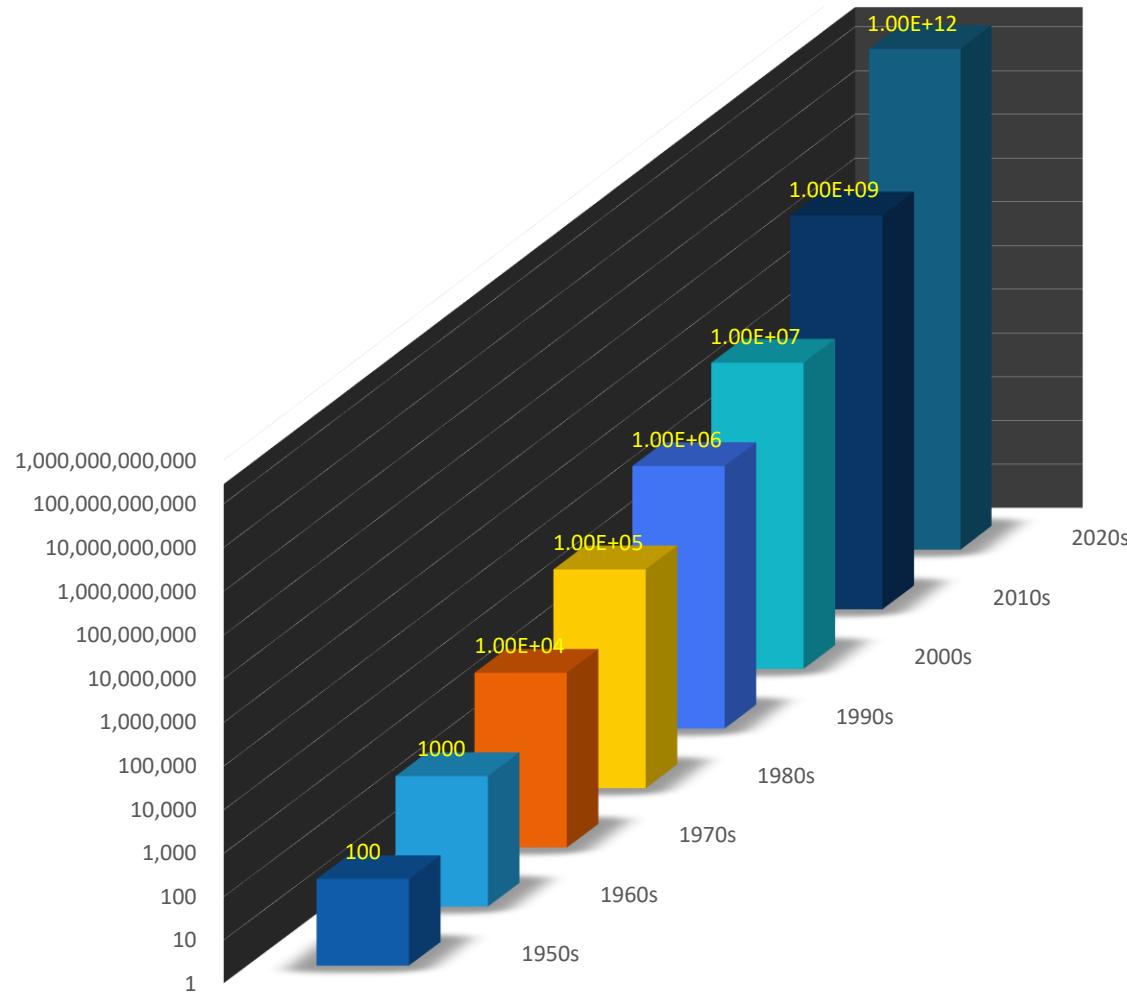
最优算法



软件投资

Size of Simulation

Problem sizes that can be handled in numerical simulation



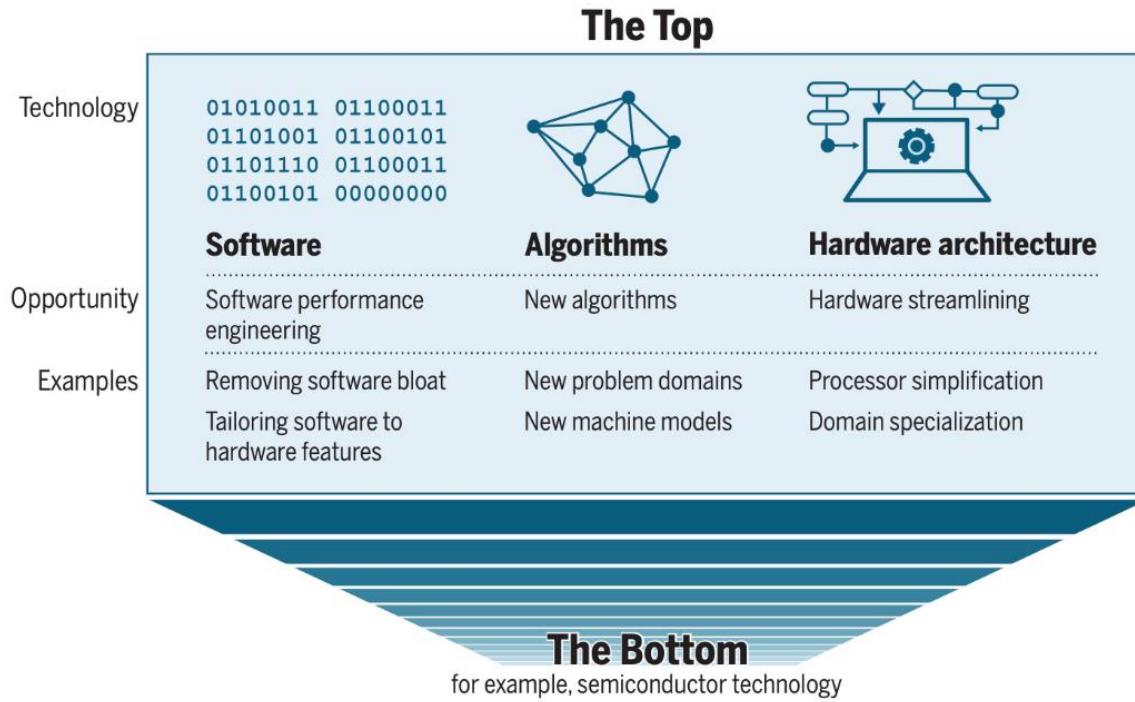
Ref: Manolis Papadrakakis, National Technical University, Greece, "Mastering the Computational Challenges for Solving Large-Scale Problems in Simulation-Based Science and Engineering", CACM talk, 2022

Driving Forces

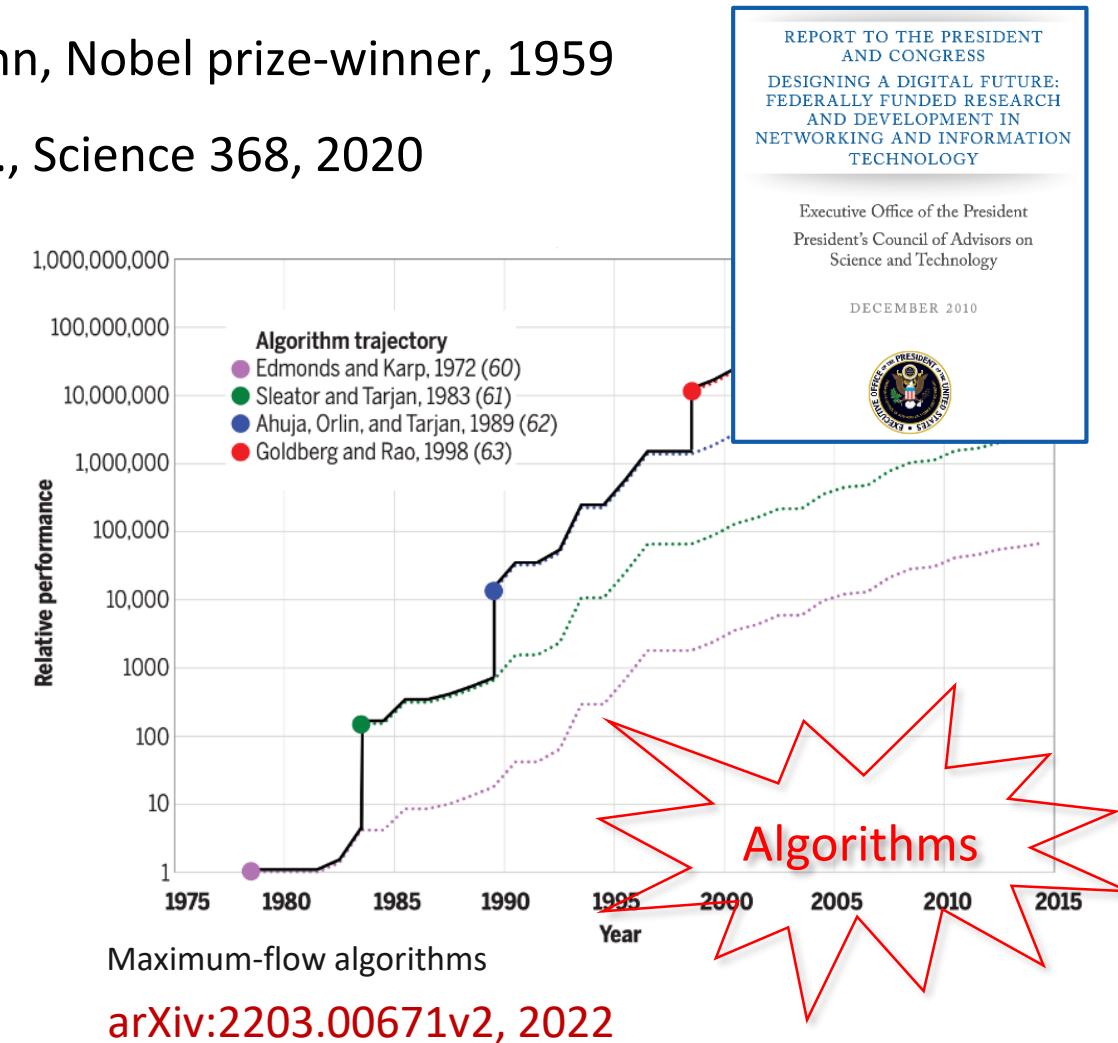
- Hardware improvement
- Algorithm development
- Demand of scientific discovery

Room for Improvement

- ~~"There's plenty of room at the bottom"~~, R. Feynmann, Nobel prize-winner, 1959
- "There's plenty of room at the top", Leiserson, et al., Science 368, 2020



Performance gains after Moore's law ends. In the post-Moore era, improvements in computing power will increasingly come from technologies at the "Top" of the computing stack, not from those at the "Bottom", reversing the historical trend.



Implementation of Algorithms

Table 1. Speedups from performance engineering a program that multiplies two 4096-by-4096 matrices. Each version represents a successive refinement of the original Python code. “Running time” is the running time of the version. “GFLOPS” is the billions of 64-bit floating-point operations per second that the version executes. “Absolute speedup” is time relative to Python, and “relative speedup,” which we show with an additional digit of precision, is time relative to the preceding line. “Fraction of peak” is GFLOPS relative to the computer’s peak 835 GFLOPS. See Methods for more details.

Version	Implementation	Running time (s)	GFLOPS	Absolute speedup	Relative speedup	Fraction of peak (%)
1	Python	25,552.48	0.005	1	—	0.00
2	Java	2,372.68	0.058	11	10.8	0.01
3	C	542.67	0.253	47	4.4	0.03
4	Parallel loops	69.80	1.969	366	7.8	0.24
5	Parallel divide and conquer	3.80	36.180	6,727	18.4	4.33
6	plus vectorization	1.10	124.914	23,224	3.5	14.96
7	plus AVX intrinsics	0.41	337.812	62,806	2.7	40.45

- Compiler optimization; loop ordering; parallel loops
- Tiling; cache-oblivious divide-and-conquer;
- Vectorization; AVX intrinsic
- Leiserson & Shun, MIT Open Course 6.172

↑ 366x
↓ 174x

Source: There's plenty of room at the Top:
What will drive computer performance after
Moore's law?

Science 368 (6495), June, 2020
<http://science.sciencemag.org/content/368/6495/eaam9744>

MKL

Scale A Practical Application

自由度数从“亿”扩展到“百亿” 意味着什么？ 并不仅规模是大了 **100倍** 而已！



... helping industry break through barriers
in massively parallel computing ...

Bill Grop, NCSA Director,
UIUC, President of IEEE
Computer Society

2010

GigaPowers

3600 CPU核, 油藏模拟

2015

我们的模拟器

10000 CPU核, 油藏模拟

2016

TeraPowers

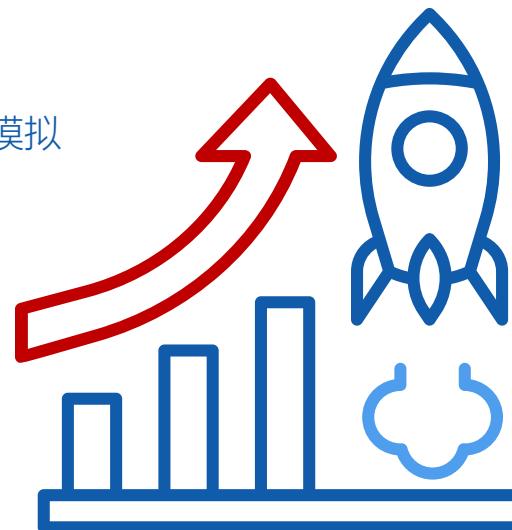
150000 CPU核, 盆地模拟

2017

EMPowers

716800 CPU核, 油藏模拟

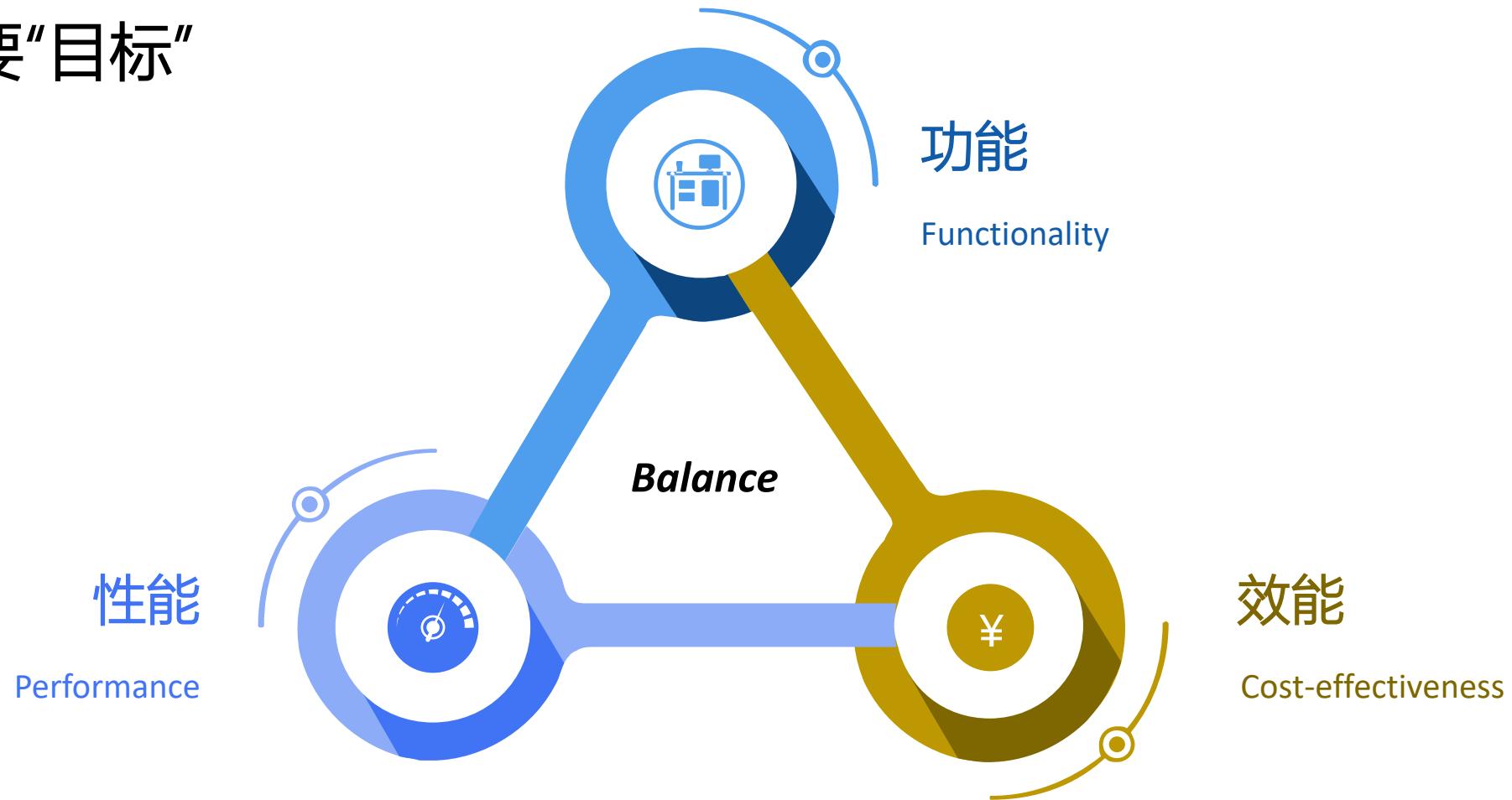
大规模油藏数值模拟器简史



- 更复杂的物理
- 更强的非线性
- 更强的耦合性
- 更小的时间步
- 更多的牛顿步
- 更多次的计算
- 更复杂的机器

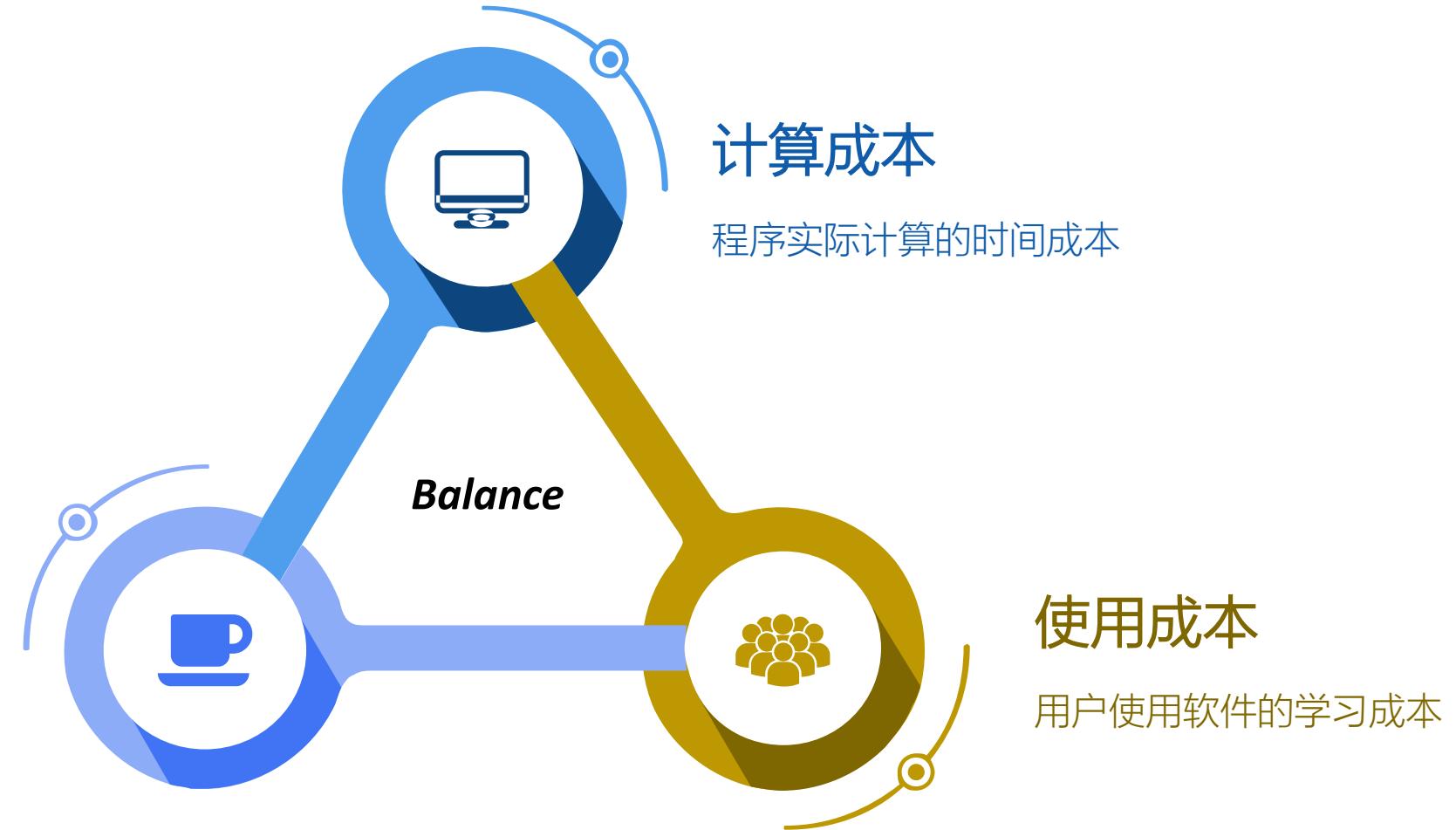
How Much Do We Expect

三个主要“目标”



How Much Effort To Put In

三个主要“成本”



Main Focus: Algebraic Solvers



- Direct and iterative solvers for sparse linear systems
- Several methods for non-symmetric problems
- Several methods for nonlinear problems
- Algorithm precision and mixed-precision algorithms
- Communication hiding and avoiding algorithms
- Fault resilience and reliability of iterative solvers
- Robustness and adaptivity of iterative solvers

Gordon Moore:

WHATEVER HAS BEEN DONE, CAN BE OUTDONE

Reading and Thinking

REVIEW

COMPUTER SCIENCE

There's plenty of room at the Top: What will drive computer performance after Moore's law?

Charles E. Leiserson¹, Neil C. Thompson^{1,2*}, Joel S. Emer^{1,3}, Bradley C. Kuszmaul^{1†}, Butler W. Lampson^{1,4}, Daniel Sanchez¹, Tao B. Schardl¹

The miniaturization of semiconductor transistors has driven the growth in computer performance for more than 50 years. As miniaturization approaches its limits, bringing an end to Moore's law, performance gains will need to come from software, algorithms, and hardware. We refer to these technologies as the "Top" of the computing stack to distinguish them from the traditional technologies at the "Bottom": semiconductor physics and silicon-fabrication technology. In the post-Moore era, the Top will provide substantial performance gains, but these gains will be opportunistic, uneven, and sporadic, and they will suffer from the law of diminishing returns. Big system components offer a promising context for tackling the challenges of working at the Top.

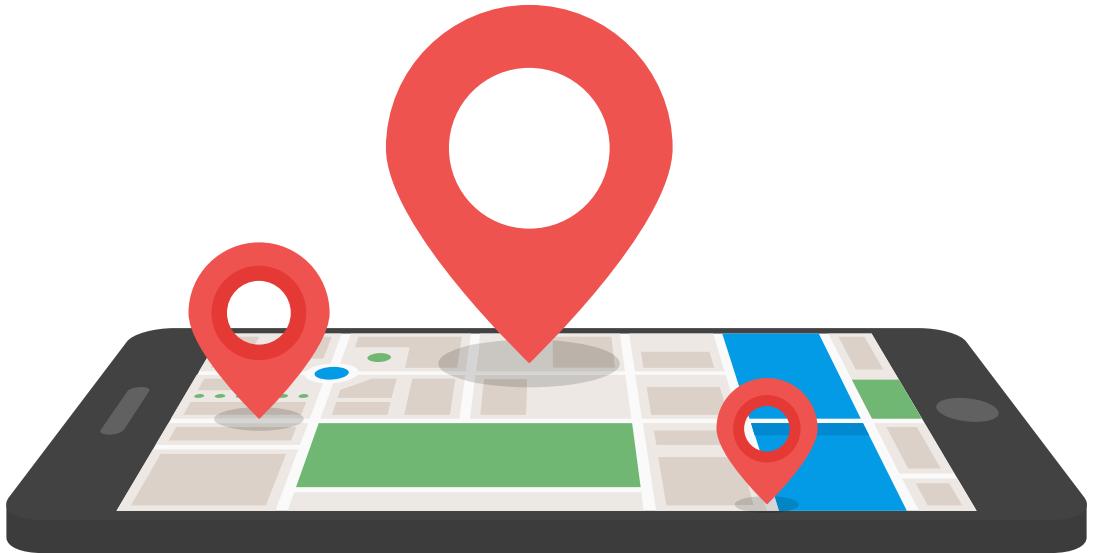
- What's your application area?
- Do you do numerical simulation?
- Do you see room for improvement in your simulation? How?
- How much time are you willing to invest on algorithm/implementation?
- Do you think “computational science” is science? Why?
- Do you think “computer science” is science? Why?

Contact Me

- Office hours: Mon 14:00—15:00
- Walk-in or online with appointment
- zhangcs@lsec.cc.ac.cn
- <http://lsec.cc.ac.cn/~zhangcs>

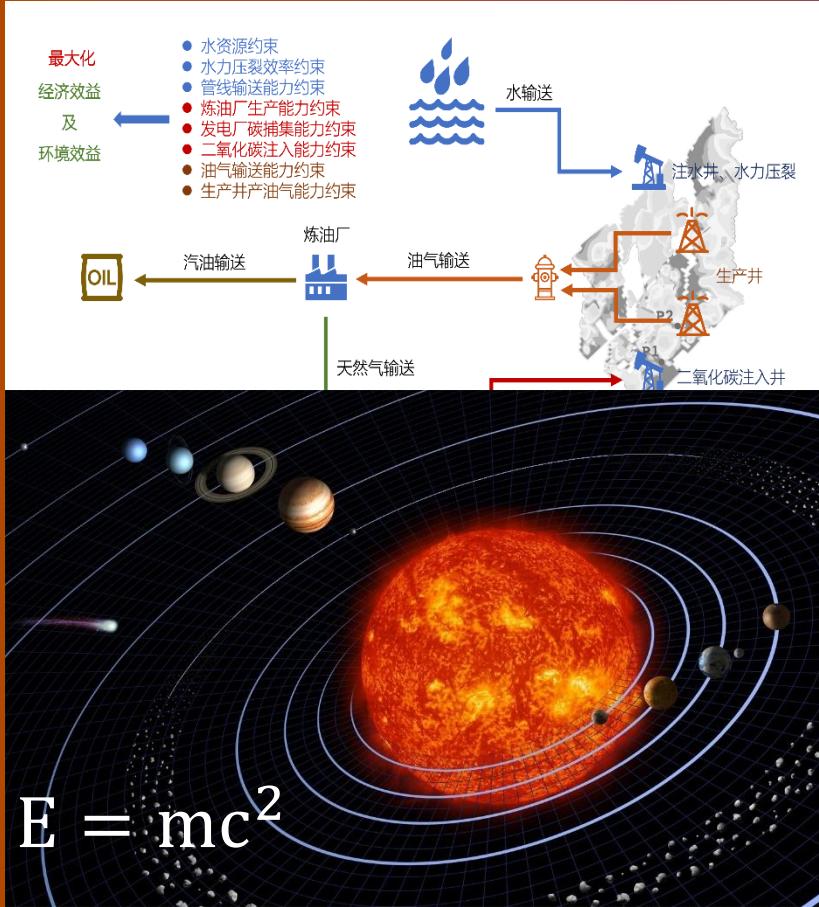
My sincere gratitude to:

Xiaowen Xu, Tao Cui, Bin Dai, Shizhe Li



Review

Applications of large-scale simulation



The diagram shows a complex network of energy and resource flow. On the left, a vertical stack of icons represents constraints: water resources, hydrofracturing efficiency, pipeline delivery, oil refinery production, power plant carbon capture, oil/gas delivery, and oil/gas well production. To the right, a map illustrates the flow of water (水输送), oil (OIL), gas (天然气输送), and carbon dioxide (二氧化碳注入井) through a network of wells (生产井) and processing facilities (炼油厂). A legend indicates symbols for water, oil, gas, and carbon dioxide. At the bottom, the equation $E = mc^2$ is displayed against a background of celestial bodies and a grid.

Science & Engineering

Applied Mathematics
Algorithm Design
Software Engineering
Performance Engineering
Hardware Architecture Design

Large-scale parallel computing



The image features a white Airbus A380 aircraft flying against a blue gradient background. The aircraft's body has the text "AIRBUS A380" and "More passenger space". Below the aircraft, a "VS" versus symbol is positioned above a cluster of eight white computer server racks, symbolizing the competition or scale of parallel computing resources.

中国科学院大学
夏季强化课程
2022

**Fast Solvers for
Large Algebraic Systems**

THANKS

Chensong Zhang, AMSS

<http://lsec.cc.ac.cn/~zhangcs>

Release version 2022.06.22